

# 電子類元件 零件承認書文件 CHECK LIST

零件廠商：UPI

品名規格：PWM uP9512RQGJ UPI

技嘉料號：10TA1-609512-00R

項次	文件項目
<b>Data Sheet 檢核項目</b>	
1	DATASHEET (含機構尺寸、 <b>端子腳鍍層材質</b> 、 <b>MSL Report</b> )
2	零件 Making 文字面說明
3	零件 Part Number 說明
4	零件 Qualification Test Report
5	料件包裝方式及包裝 Label 之零件 Part number 說明
6	UL Safety Report (If Request )
7	零件耐溫焊接 Profile(包含最高耐焊溫度,時間，焊接/過爐次數與曲線圖)。 <b>註 2</b>
8	零件樣品 20PCS(Chipset 等高單價，至少 1PCS)
9	<b>電子零件承認基本調查表</b> 。 <b>註 3</b>
10	以上資料電子檔為 PDF 檔，且是同 1 個 File
<b>GSCM 綠色產品管理系統-物料管制文件檢核清單</b>	
物料管制文件 1	GSCM 綠色產品管理系統：零件照片
物料管制文件 2	GSCM 綠色產品管理系統：不使用禁用物質證明書 (保證書)。 <b>註 4</b>
物料管制文件 3	GSCM 綠色產品管理系統：Data Sheet
<b>GSCM 綠色產品管理系統-MCD 表格</b>	
MCD 表格	物質內容宣告表格 (Material Content Declaration, MCD)
<b>其他文件 (僅適用電阻、電容類之系列元件)</b>	
附件 1	危害物質測試報告 Test Report of Hazardous Substances。 <b>註 5</b>
附件 2	元件調查表 Component Composition Table

- ※ 1. 各項說明文件內容應明訂零件交貨時之規格、方式；如捲盤、文字印刷為雷射或油墨等
- ※ 2. 零件耐溫焊接 Profile 需附相關測試報告 (國際認證之實驗室資格單位所出具之測試報告)
- 2.1. 基本需符合 JEDEC 規範
- 2.2. Ambient Temp. (Reflow Temp endure): >225°C, 70 sec. 零件塑膠材質需 PA9T(含)等級以上
- 2.3. PASTE IN HOLE 零件塑膠材質需 PA9T(含)等級以上
- ※ 3. 電子零件適用(技嘉)料號：**積體電路(IC) 10H\*,10T\*,10I\*,10D\*,10G\*,11T\***  
**非 IC 類：10C\*,11C\*,10L\*,11L\*,10X\*,11X\*,10R\*,11B\***
- ※ 4. 物料管制文件 2：網通事業群之所屬料件須一併提交 “不使用禁用物質證明書(保證書)+ REACH 調查表”

※ 5. 危害物質測試報告 Test Report of Hazardous Substances：泛指為具有 ISO/IEC 17025 國際認證之實驗室資格單位所出具之測試報告

## 電子零件承認基本調查表

一、原物料規格/來源			
項次	部位名稱/規格	材質	原物料來源產地
1	CHIP	金屬	TAIWAN
2	DIE ATTACH	EPOXY	JAPAN
3	LEAD FRAME	金屬	JAPAN
4	BONDING WIRE	金屬	KOREA
5	MOLDING COMPOUND	EPOXY	TAIWAN
6	PLATING	鍍錫	TAIWAN

二、晶圓廠(非 IC 類免填)					
項次	工廠名稱	生產產地	Wafer (吋)	投產率(%)	自有/外包
1	(MAX)鉅晶電子	TW	8	100%	外包

三、封裝廠(IC 類)；成品之生產製造工廠(非 IC 類)				
項次	工廠名稱	生產產地	投產比率(%)	自有/外包
1	GTK(超豐電子)	TW	50%	外包
2	ASE-KS(日月光-昆山)	KS	50%	外包
3				

四、產能	
總產能(月/PCS)	可供技嘉產能(月/PCS)
NA	NA

- ※ 1. IC 類之晶圓廠、封裝廠之所有 AVL 請均表列，並提供相關資訊與文件。當異動 (包含 AVL 或相關資訊文件之異動) 時，請主動通知技嘉 Sourcer 與 RD 承認單位，並更新文件
- ※ 2. 非 IC 類零件之成品生產製造工廠之所有 AVL 請均表列，並提供相關資訊與文件。當異動 (包含 AVL 或相關資訊文件之異動) 時，請主動通知技嘉 Sourcer 與 RD 承認單位，並更新文件
- ※ 3. 以上資訊欄位若有不足，可自行增加行數

## 8/7/6/5/4/3/2/1-Phase Synchronous-Rectified Buck Controller with SMBus Digital Interface

### General Description

The uP9512R is an 8/7/6/5/4/3/2/1-phase PWM controller specifically designed to provide high-precision output voltage system for next generation GPUs. The uP9512R provides programmable output voltage and active voltage positioning functions to adjust the output voltage as a function of the load current, so it is optimally positioned for a load current transient.

The uP9512R supports NVIDIA Open Voltage Regulator type 4i+ with PWMVID feature. The PWMVID input is buffered and filtered to generate accurate reference voltage and the output voltage is precisely regulated to the reference input. The integrated SMBus interface provides user the flexibility to optimize the performance and efficiency.

The uP9512R uses per-channel inductor DCR current sensing for channel current balance and channel current limit. The continuous total DCR current sensing is used for load line programming and total output current protection. The uP9512R also provides hardware setting to adjust the operating phase number in different load current state.

Other features include adjustable soft-start, under voltage protection, over voltage protection and power good output. The uP9512R is available in a VQFN5x5-40L package.

### Ordering Information

Order Number	Package	Top Marking
uP9512RQGJ	VQFN5x5 - 40L	uP9512R

Note:

- (1) Please check the sample/production availability with uPI representatives.
- (2) uPI products are compatible with the current IPC/JEDEC J-STD-020 requirements. They are halogen-free, RoHS compliant and 100% matte tin (Sn) plating that are suitable for use in SnPb or Pb-free soldering processes.

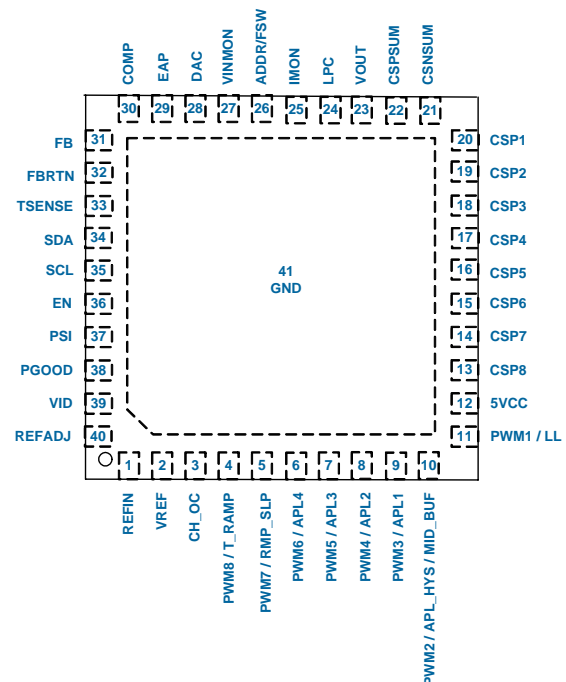
### Applications

- Middle-High End GPU Core Power Supplies

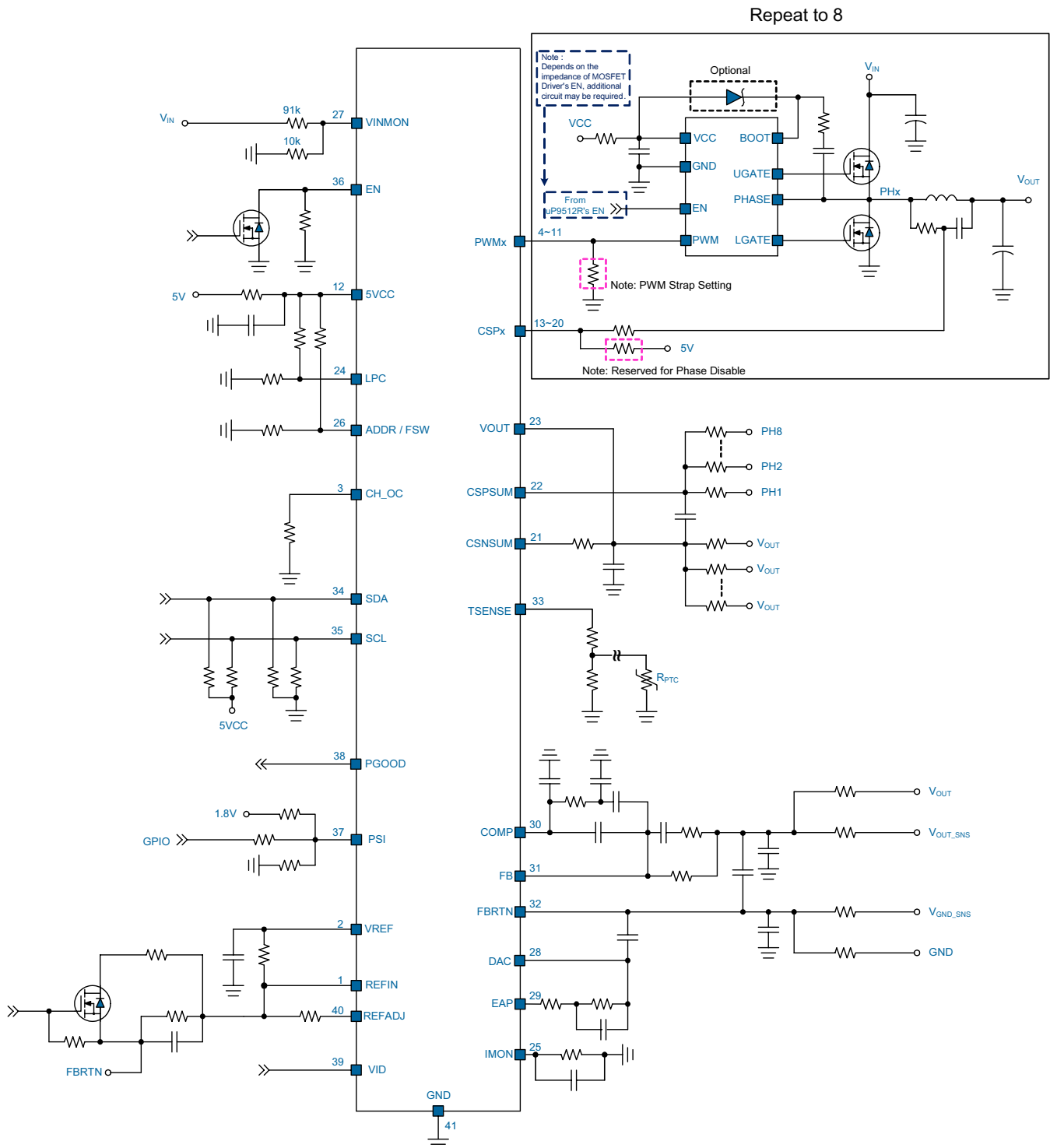
### Features

- Support NVIDIA's Open VReg Type 4i+ PWMVID Technology
- SMBus Interface for Performance and Efficiency Optimization
  - Dynamic Programmable VR Parameters
  - Programmable Protection Thresholds
  - VR Output Reporting
- Selectable 8/7/6/5/4/3/2/1-Phase Operation by Hardware Setting
- Support up to 2MHz Operation Frequency
- Continuous Inductor DCR Current Sensing
- Auto-Phase Shedding
- Adjustable Soft-Start Time
- Power State Input (PSI)
- Power Good Indication
- Channel Current Limit Protection
- Total Output Over Current Protection
- Over/Under Voltage Protection
- Over Temperature Protection
- RoHS Compliant and Halogen Free

### Pin Configuration



## Typical Application Circuit



## Functional Pin Description

No.	Name	Pin Function
1	REFIN	<b>Reference Input.</b> Connect this pin to an external reference voltage through a resistor or connect to the output of the REFADJ circuit.
2	VREF	<b>Reference Voltage.</b> 2V LDO voltage output pin. Connect an at least 1 uF decoupling capacitor between this pin and GND.
3	CH_OC	<b>Channel Current Limit.</b> Connect a resistor from this pin to GND to set the per-channel current limit threshold.
4	PWM8/T_RAMP	<b>Phase 8 PWM Output and Soft-Start Time.</b> It outputs a PWM logic signal for external MOSFET driver and it is also used to set the soft-start time. Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to GND to set the soft-start time. The resistor value should be greater than 15kΩ.
5	PWM7/RMP_SLP	<b>Phase 7 PWM Output and RAMP Slope.</b> It outputs a PWM logic signal for external MOSFET driver and it is also used to set the slope of internal RAMP signal. Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to GND to set the RAMP slope. The resistor value should be greater than 15kΩ.
6	PWM6/APL4	<b>Phase 6 PWM Output and Auto-Phase Shedding Threshold 4.</b> It outputs a PWM logic signal for external MOSFET driver and it is also used to set the auto-phase shedding threshold 4. Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to GND to set the auto-phase shedding threshold 4. The resistor value should be greater than 15kΩ.
7	PWM5/APL3	<b>Phase 5 PWM Output and Auto-Phase Shedding Threshold 3.</b> It outputs a PWM logic signal for external MOSFET driver and it is also used to set the auto-phase shedding threshold 3. Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to GND to set the auto-phase shedding threshold 3. The resistor value should be greater than 15kΩ.
8	PWM4/APL2	<b>Phase 4 PWM Output and Auto-Phase Shedding Threshold 2.</b> It outputs a PWM logic signal for external MOSFET driver and it is also used to set the auto-phase shedding threshold 2. Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to GND to set the auto-phase shedding threshold 2. The resistor value should be greater than 15kΩ.
9	PWM3/APL1	<b>Phase 3 PWM Output and Auto-Phase Shedding Threshold 1.</b> It outputs a PWM logic signal for external MOSFET driver and it is also used to set the auto-phase shedding threshold 1. Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to GND to set the auto-phase shedding threshold 1. The resistor value should be greater than 15kΩ.
10	PWM2/APL_HYS/ MID_BUF	<b>Phase 2 PWM Output, Hysteresis of Auto-Phase Shedding and PWM Middle State Mode Control.</b> It outputs a PWM logic signal for external MOSFET driver and it is also used to set the hysteresis of auto-phase shedding and PWM middle state mode selection. Connect this pin to the PWM input of external MOSFET driver. Connect a resistor from this pin to GND to set the hysteresis of auto-phase shedding and selects the PWM middle state mode. The resistor value should be greater than 15kΩ.
11	PWM1/LL	<b>Phase 1 PWM Output and Load Line.</b> It outputs a PWM logic signal for external MOSFET driver and it is also used to program the DC load line enable threshold. Connect a resistor from this pin to GND to set the DC load line enable threshold. The resistor value should be greater than 15kΩ.

## Functional Pin Description

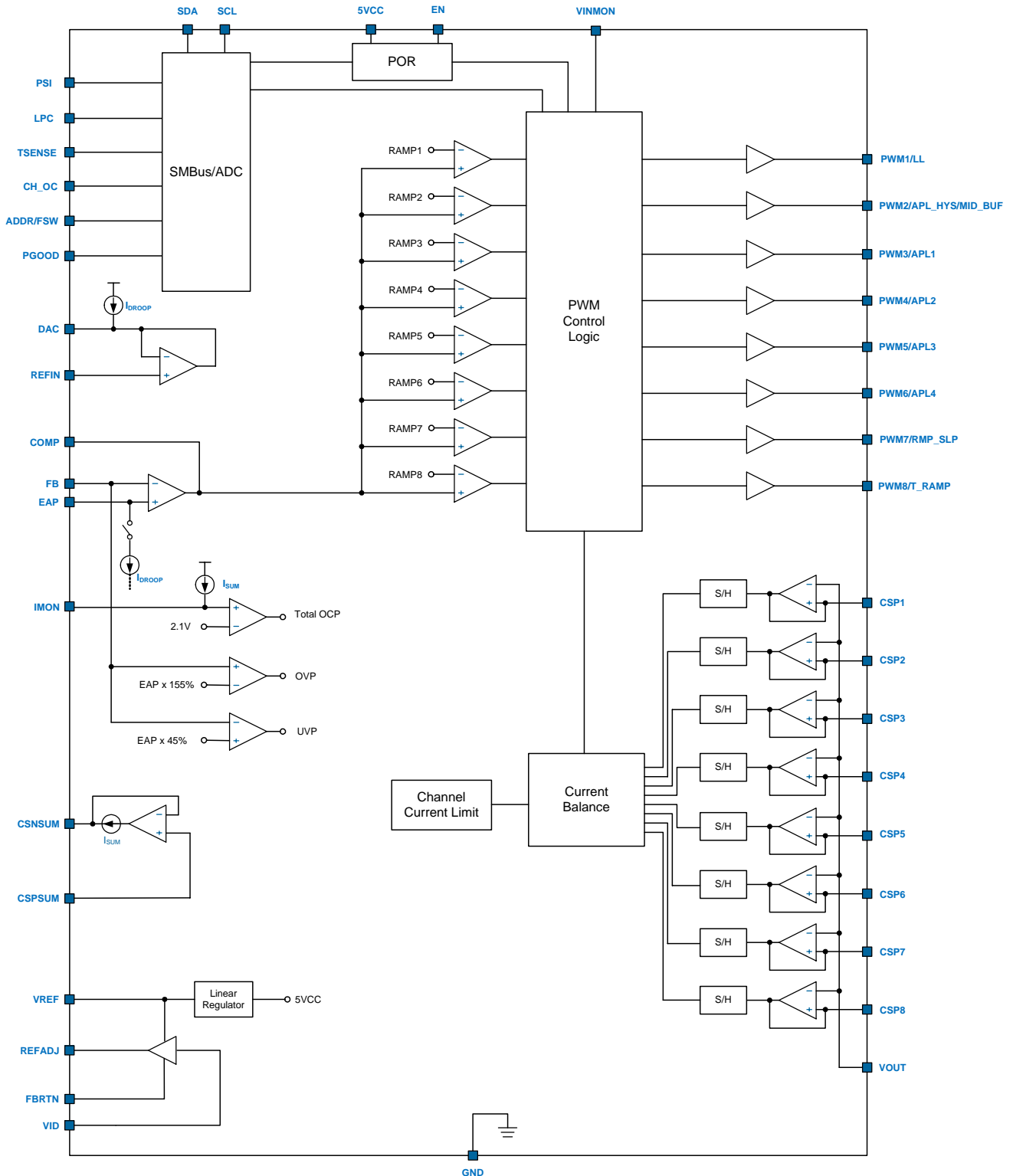
No.	Name	Pin Function
12	5VCC	<b>Supply Input for the IC.</b> Connect this pin to a 5V voltage source with RC filter. Connect this pin to a 5V supply and decouple with a ceramic capacitor of 1uF minimum.
13	CSP8	<b>Non-Inverting Input of Current Sensing Amplifier for Phase 8.</b> This pin is used for differentially sensing phase 8 output current . Connect this pin to the node between the RC current sense elements.
14	CSP7	<b>Non-Inverting Input of Current Sensing Amplifier for Phase 7.</b> This pin is used for differentially sensing phase 7 output current . Connect this pin to the node between the RC current sense elements.
15	CSP6	<b>Non-Inverting Input of Current Sensing Amplifier for Phase 6.</b> This pin is used for differentially sensing phase 6 output current . Connect this pin to the node between the RC current sense elements.
16	CSP5	<b>Non-Inverting Input of Current Sensing Amplifier for Phase 5.</b> This pin is used for differentially sensing phase 5 output current . Connect this pin to the node between the RC current sense elements.
17	CSP4	<b>Non-Inverting Input of Current Sensing Amplifier for Phase 4.</b> This pin is used for differentially sensing phase 4 output current . Connect this pin to the node between the RC current sense elements.
18	CSP3	<b>Non-Inverting Input of Current Sensing Amplifier for Phase 3.</b> This pin is used for differentially sensing phase 3 output current . Connect this pin to the node between the RC current sense elements.
19	CSP2	<b>Non-Inverting Input of Current Sensing Amplifier for Phase 2.</b> This pin is used for differentially sensing phase 2 output current . Connect this pin to the node between the RC current sense elements.
20	CSP1	<b>Non-Inverting Input of Current Sensing Amplifier for Phase 1.</b> This pin is used for differentially sensing phase 1 output current . Connect this pin to the node between the RC current sense elements.
21	CSNSUM	<b>Inverting Input of Total Current Sense Amplifier.</b>
22	CSPSUM	<b>Non-Inverting Input of Total Current Sense Amplifier.</b>
23	VOUT	<b>Output Voltage.</b> Inverting input of current sensing amplifier for phase1~phase8. Connect this pin directly to output voltage plane.
24	LPC	<b>Low Phase Count.</b> Connect a voltage divider from 5VCC to this pin to set the operation phase number of Warm Boot and Cold Boot. <b>Do NOT</b> connect any decoupling capacitor to this pin.
25	IMON	<b>Output Current Monitor.</b> The output current of this pin is proportional to the total load current. The total load current is sensed and flows out of this pin, and a resistor from this pin to GND makes the IMON voltage proportional to the total output current. The IMON voltage is monitored for total output over current protection. A capacitor can be connected from IMON to GND to adjust the response time of IMON.
26	ADDR/FSW	<b>SMBus Device Address and Operation Frequency.</b> Connect a voltage divider from 5VCC to this pin to select the SMBus device address and operation frequency. <b>Do NOT</b> connect any decoupling capacitor to this pin.

## Functional Pin Description

No.	Name	Pin Function
27	VINMON	<b>Power Stage Input Voltage Monitor.</b> Connect this pin to the power stage input VIN with a voltage divider. The controller senses the voltage on this pin for power stage input voltage VIN detection. It is recommended to use resistor divider with 1/10 dividing ratio from VIN. For example, use 91kΩ/10kΩ resistor divider is a good practice.
28	DAC	<b>DAC Output.</b> The output voltage of this pin is the reference voltage.
29	EAP	<b>Non-Inverting Input of the Error Amplifier.</b> Connect a resistor between this pin and DAC pin to set the droop (load line) function.
30	COMP	<b>Output of Control Loop Error Amplifier.</b>
31	FB	<b>Inverting Input of the Error Amplifier.</b>
32	FBRTN	<b>Output Voltage Feedback Return.</b> Inverting input to the differential voltage sense amplifier. FBRTN is the reference point in DAC output voltage measurement. Connect this pin directly to the GPU output voltage feedback return sense point.
33	TSENSE	<b>Thermal Monitoring Input.</b> Connect a specified positive temperature coefficient (PTC) thermistor network from this pin to GND for VR temperature sensing.
34	SDA	<b>SMBus Data Input.</b> This pin is input or output of serial bus data signal. If the SMBus is not available, this pin can be a hardware setting pin for single phase operation mode selection. Find the detail description in "SMBus (SCL & SDA)" section.
35	SCL	<b>SMBus Clock Input.</b> This pin receives serial bus clock signal input. If the SMBus is not available, this pin can be a hardware setting pin for single phase operation mode selection. Find the detail description in "SMBus (SCL & SDA)" section.
36	EN	<b>Enable.</b> Connect a 10kΩ resistor from this pin to ground to enable the PWM strap function and place this resistor close to the controller. To disable PWM strap function, use 24kΩ instead. <b>Do NOT</b> use resistance values other than the value specified here. <b>Do NOT</b> connect any capacitor directly to this pin. Refer to the typical application circuit, it is recommended to use a MOSFET with its drain connected to EN pin without a pull-up resistor for power sequence control. <b>Do NOT</b> connect EN pin directly to a voltage source for sequence control.
37	PSI	<b>Power Saving Input.</b> An input pin receiving power saving control signal from GPU.
38	PGOOD	<b>Power Good Indication.</b> Connect this pin to a voltage source with a pull-up resistor.
39	VID	<b>VID.</b> PWMVID input pin.
40	REFADJ	<b>Reference Adjustment.</b> PWMVID output pin. Connect this pin with an RC integrator to generate REFIN voltage.
Exposed Pad		<b>Ground.</b> The exposed pad is the ground of logic control circuits, it must be soldered to a large PCB and connected to GND.



**Functional Block Diagram**



## Functional Description

### Power On Reset (POR)

Figure 1 shows the power ready detection circuit. The 5VCC voltage is monitored for power on reset with typically 4.3V threshold at its rising edge. When 5VCC is ready, the controller waits for EN to start up. When EN pin is driven above 0.2V, the controller begins its start up sequence. When EN pin is driven below 0.1V, the controller will be turned off, and it will clear all fault states to prepare to next soft-start once the controller is re-enabled.

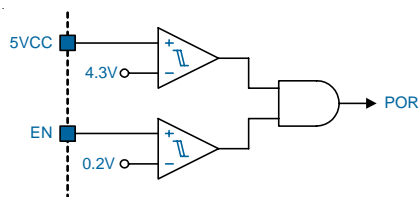


Figure 1. Circuit of Power Ready Detection

### Power Input Monitor

VINMON is the power stage input voltage sense pin. Connect this pin to power stage input voltage (VIN) with a voltage divider and always keep VINMON as 1/10 of power stage input voltage. When VINMON less than typically 0.2V at POR, the uP9512R will force start up at single phase and disables the cold boot, warm boot, PSI and auto-phase function. Once this condition is triggered, it can only be reset by re-POR or EN restart.

### Enable Control

The EN pin controls the enable and disable of this device. The resistor  $R_{EN}$  connected between EN pin to ground is used to implement this function. It is recommended to use a small MOSFET with its drain connected to EN pin without pull up resistor for power sequence control as shown in Figure 2. Precaution should be taken while implementing the power sequence circuit to EN pin. **Do NOT** use other resistance value other than values specified in the PWM Strap section and **do NOT** connect EN pin directly to a voltage source. **Do NOT** connect EN pin directly to any sequencing circuit of the system. Make sure the slew rate of the gate signal (EN#) of Q1 is fast and not affected by any additional circuit.

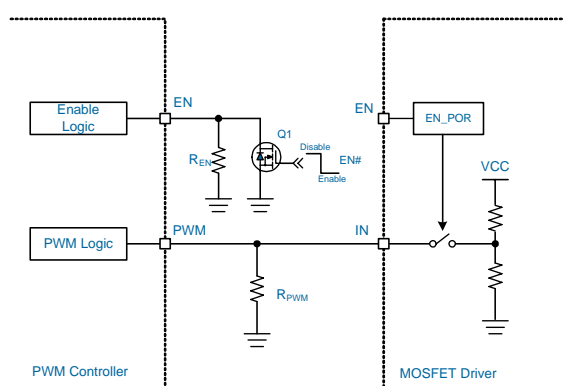


Figure 2. Enable Sequence Control

### PWM Strap Function

The uP9512R implements PWM strap function to provide more functional programming in a limited pin out. The PWM strap function can be controlled by the  $R_{EN}$  resistor connected from EN pin to GND. Use  $R_{EN}=10k\Omega$  to activate the PWM strap function and use  $R_{EN}=24k\Omega$  for function disable. To ensure correct PWM strap function setting. The input impedance of PWM pin of companion MOSFET driver should be in high-impedance state during the initial setting period prior to soft-start (Figure 2). Otherwise all the function setting by PWM pins can only be done via SMBus interface.

### Soft Start and Power Up Sequence

The uP9512R features a programmable soft start function to limit the surge current from power supply input. Controller starts the soft-start process right on  $V_{EN} > 0.2V$  with typical 550us initialization time ( $T_{INIT}$ ). The output voltage ramp up time ( $T_{RAMP}$ ) during soft start period is determined by the resistor  $R_{PWM8}$  connected from PWM8 pin to GND. Table 1 shows the  $T_{RAMP}$  time and recommended  $R_{PWM8}$  resistance.

Table 1.  $T_{RAMP}$  Time and Recommended  $R_{PWM8}$

$R_{PWM8}$	$T_{RAMP}$
39k $\Omega$	160us
100k $\Omega$	320us
150k $\Omega$	1.28ms
unstuffed	640us

If  $R_{PWM8}$  resistor is unstuffed, the output voltage ramp up time during soft-start period is typical 640us. If there is no fault detected at the end of soft-start, the controller then asserts PGOOD when the output voltage reaches its target without delay. Figure 3 shows the power up sequence of the uP9512R.

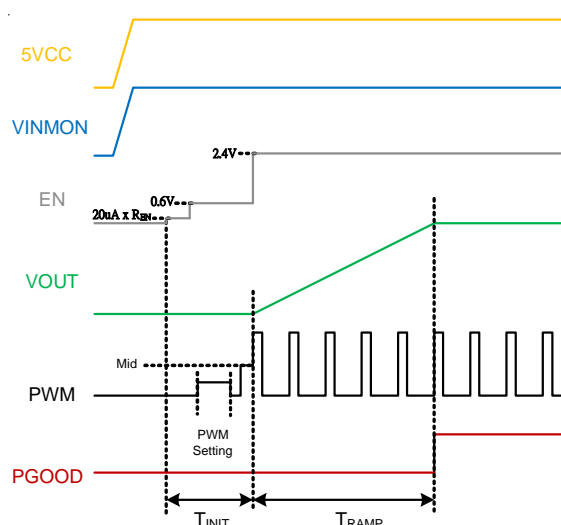


Figure 3 Power Up Sequence

## Functional Description

## PWMVID Function

The PWMVID signal from GPU is applied to the VID pin, which is the input pin of the internal buffer. This buffer plays the role of level shifting, and the output of this buffer is injected into the external RC integrator to generate REFIN voltage, which can be calculated as:

$$V_{REFIN} = V_{VREF} \times D \times \frac{R2 // (R3 + R4 + R5)}{R1 + R2 // (R3 + R4 + R5)} \times \frac{R4 + R5}{R3 + R4 + R5} + V_{VREF} \times \frac{R1 // (R3 + R4 + R5)}{R2 + R1 // (R3 + R4 + R5)} \times \frac{R4 + R5}{R3 + R4 + R5}$$

where  $V_{REFIN}$  is the DC voltage of REFIN,  $V_{VREF}$  is the voltage of VREF (typically 2V), and D is the duty cycle of PWMVID input. The VREF pin is an internal LDO, therefore an output decoupling capacitor is required. Recommend connecting at least a 1  $\mu$ F capacitor from VREF pin to local GND.

## Boot Mode and Standby Mode

The PWMVID structure includes two operation modes: boot mode and standby mode. **During boot mode, controller ignores the PWMVID signal before PGOOD signal goes high and the REFADJ pin enters high impedance state.** The REFIN voltage during boot mode can be calculated as:

$$V_{REFIN,BOOT} = V_{VREF} \times \frac{R4 + R5}{R2 + R3 + R4 + R5}$$

During standby mode, other than GPU stopping the PWMVID transaction, an external system standby signal additionally controls the entry of standby mode. An additional external switch should be connected in parallel with the original PWMVID resistors as shown in Figure 4 to generate the standby mode voltage:

$$V_{REFIN,STDBY} = V_{VREF} \times \frac{(R3+R4+R5) // R_{STDBY}}{R2 + (R3+R4+R5) // R_{STDBY}} \times \frac{R4+R5}{R3+R4+R5}$$

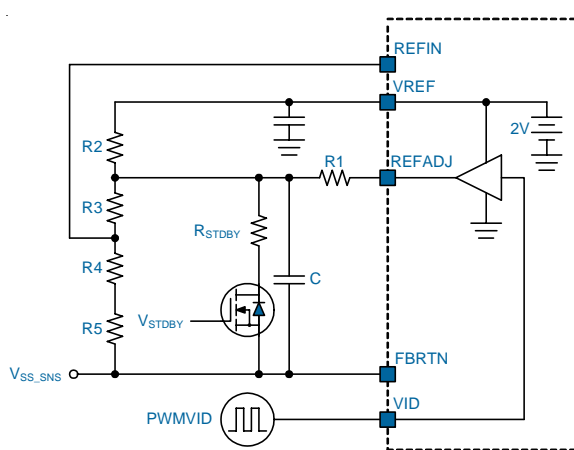


Figure 4. PWMVID Structure

## Channel Current Balance

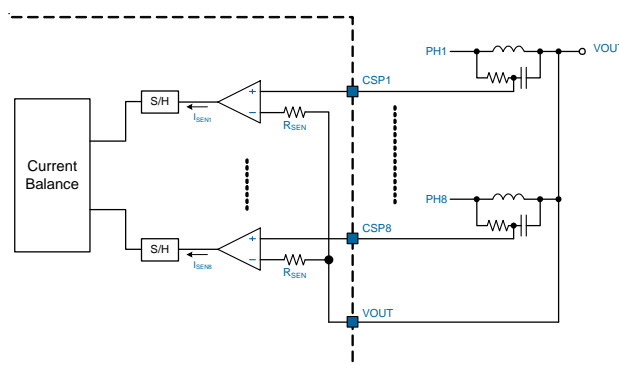


Figure 5. Current Balance Circuit

The uP9512R senses each phase current through CSPx pin for current balancing. The phase current signal is sampled and held when the low-side MOSFETs are turned on. The sensed current  $I_{SENx}$  can be determined by the following equation:

$$I_{SENx} = \frac{\Delta V_{CSPx}}{R_{SEN}}$$

Where  $I_{SENx}$  is the sampled and held phase current signal,  $\Delta V_{CSPx}$  is the differential voltage between CSPx and VOUT and the  $R_{SEN}$  is internal sense resistor which is typical  $655\Omega$ . The sensed current  $I_{SENx}$  is mirrored to the current balance circuit, comparing between each other, and generating current adjusting signals for each phase. The current balance circuit increases the duty cycle of the phase whose phase current is smaller than others and decrease the duty cycle of the phase whose phase current is larger than others.

### Total Load Current Sense

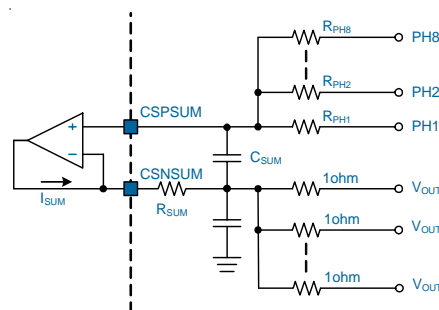


Figure 6. Total Load Current Sense

The uP9512R uses a low input offset current sense amplifier (CSA) to sense the total load current flowing through inductors for droop function by CSPSUM and CSNSUM as shown in Figure 6.

## Functional Description

The voltage across  $C_{SUM}$  is proportional to the total load current, and the output current of CSA ( $I_{SUM}$ ) is also proportional to the total load current of the voltage regulator. The sensed current  $I_{SUM}$  represents the total output current of the regulator, and it is directly used for droop function, total output over current protection and auto-phase shedding function.  $I_{SUM}$  is calculated as follows.

$$I_{SUM} = \frac{I_{OUT} \times \frac{R_{DC}}{N}}{R_{SUM}}$$

In this inductor current sensing topology,  $R_{PH}$  and  $C_{SUM}$  must be selected according to the equation below:

$$k \times \frac{L}{R_{DC}} = \frac{R_{PH} \times C_{SUM}}{N}$$

where  $R_{DC}$  is the DCR of the output inductor  $L$ ,  $N$  is the operation phase number. Theoretically,  $k$  should be equal to 1 to sense the instantaneous total load current. But in real application,  $k$  is usually between 1.2 to 1.8 for better load transient response. Note that the resistance value of  $R_{SUM}$  must be less than 2kΩ to ensure the current sensing circuit in normal operation.

### DC Load Line

The uP9512R implements DC load line with programmable enable threshold for user to optimize load transient performance. When DC load line is activated, the DC output voltage decreases as the output DC current increases. The enable threshold of DC load line is set by a  $R_{PWM1}$  resistor connected from PWM1 pin to GND. An  $I_{LLTH}$  current is generated by a 2V voltage source and  $R_{PWM1}$  during  $T_{INIT}$  time, it is calculated as :

$$I_{LLTH} = \frac{2V}{R_{PWM1}}$$

If the  $I_{SUM}$  current is greater than  $I_{LLTH}$  current, controller then activates the DC load line function. The  $I_{LLTH}$  current must be in the range of 10uA to 80uA ( $R_{PWM1}$  = 200kΩ to 25kΩ), out of the specified range should be avoided.

### AC Load Line

The AC load line function is used to improve the load transient response. This function only takes effect in the load transient condition when the output voltage has instantaneous change due to transient load current. It does not affect the output DC voltage when the load current is in DC condition. Connect a 16kΩ resistor ( or resistance range from 15kΩ to 18kΩ) from PWM1 to GND to enable the AC load line function. The response time of AC load line is typically 80us, and the voltage droop is generated by the  $R_{DROOP}$  resistor (see "Voltage Control Loop" section for details). The AC load line function & the response time can also be programmed via SMBus interface.

### Voltage Control Loop

Figure 7 illustrates the voltage control loop of the uP9512R.

FB and EAP are negative and positive inputs of the error amplifier respectively. The error amplifier modulates the COMP voltage ( $V_{COMP}$ ) and the duty cycle of regulator to force  $V_{FB}$  follows  $V_{EAP}$ . The  $I_{DROOP}$  current is mirrored to the EAP pin and creates a voltage at EAP pin as:

$$V_{EAP} = V_{DAC} - I_{DROOP} \times R_{DROOP}$$

$$I_{DROOP} = I_{SUM} - I_{LLTH} \text{ (if DC load line is activated)}$$

$$I_{DROOP} = I_{SUM} \text{ (if AC load line is activated)}$$

Where  $V_{DAC}$  is output of  $V_{REFIN}$ ,  $R_{DROOP}$  is an external resistor connected between DAC and EAP pins for adjusting load line slope and  $I_{DROOP}$  is a current source proportional to output current when the DC load line function is activated.

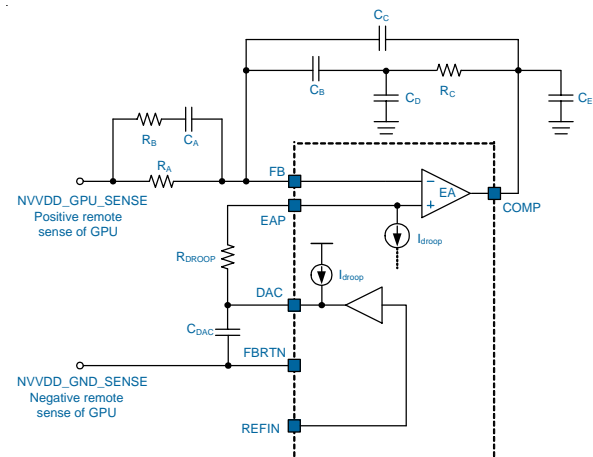


Figure 7. Voltage Control Loop

### Output Voltage Differential Sense

The uP9512R uses differential sense by a high-gain low offset error amplifier for output voltage differential sense as shown in Figure 7. The GPU voltage is sensed by the FB and FBRTN pins. FB pin is connected to the positive remote sense pin NVDD\_GPU\_SENSE of the GPU via the resistor  $R_{FB}$ . FBRTN pin is connected to the negative remote sense pin NVDD\_GND\_SENSE of GPU directly.

### Power Saving Mode

The uP9512R provides power saving features for platform designers to program platform specific power saving configuration. There are three operation modes: Full-Phase mode, Auto-Phase Shedding mode, and Low-Phase mode. The uP9512R switches between these three operation modes according to the input voltage level of the PSI pin. Figure 8 shows typical PSI application circuit, and Table 2 shows recommended PSI setting voltage level of the three operation modes. In low-phase mode, it can separate into Cold Boot Mode and Warm Boot Mode. The operation phase number of Cold Boot Mode and Warm Boot Mode is

## Functional Description

determined by LPC pin. In auto-phase shedding mode, the operation phase number will auto increase/decrease according to output loading. In Full-Phase mode, the maximum phase number of operation is determined by checking the status of CPSx pins when POR.

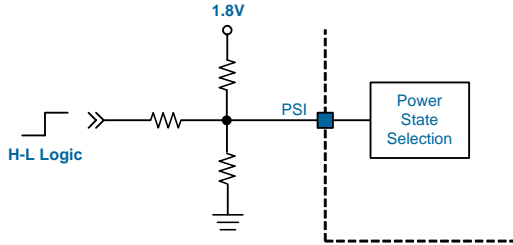


Figure 8. PSI Application Circuit

Table 2. Operation Mode and Recommended  $V_{PSI}$

Operation Mode	Recommended Voltage Setting at PSI
Full-Phase CCM Mode	1.8V
Auto-Phase Shedding Mode	1V
Low-Phase Mode	GND

### Auto-Phase Shedding

The uP9512R provides Auto-Phase Shedding function to reduce the switching and conduction losses at light load condition and enable high efficiency over a wide range of output current. Auto-Phase Shedding function is activated by two conditions:

1. PSI voltage stays at “Auto-Phase Shedding Mode”.
2. After PGOOD goes high, VID pin received the PWM-VID input signal from GPU.

Once the Auto-Phase Shedding function is activated, the uP9512R compares the  $V_{IMON}$  with APL1/APL2/APL3/APL4 threshold to decide the operation phase number dynamically. The APL1/APL2/APL3/APL4 threshold and the hysteresis can be programmed through SMBus interface. It also can be programmed by the resistor which is connected from PWM3~PWM6 pins to GND. The APL1 ~ APL4 threshold can be calculated as:

$$V_{APL1} = (10\mu A \times R_{PWM3}) / 4$$

$$V_{APL2} = (10\mu A \times R_{PWM4}) / 2$$

$$V_{APL3} = (10\mu A \times R_{PWM5})$$

$$V_{APL4} = (10\mu A \times R_{PWM6})$$

If  $V_{IMON} < V_{APL1}$ , uP9512R operates in single phase;

if  $V_{APL1} < V_{IMON} < V_{APL2}$ , uP9512R operates in dual phase;

if  $V_{APL2} < V_{IMON} < V_{APL3}$ , uP9512R operates in four phase;

if  $V_{APL3} < V_{IMON} < V_{APL4}$ , uP9512R operates in six phase;

if  $V_{IMON} > V_{APL4}$ , uP9512R operates in eight phase.

The uP9512R always keeps all-of-phase interleaved

operation.

**When setting the operating phase number of each current zone, always keep**

$$\Phi_{APL1} < \Phi_{APL2} < \Phi_{APL3} < \Phi_{APL4}$$

**Violating this rule, controller will be forced into full phase operation mode.**

The hysteresis of APLx level and the PWM middle state mode can be programmed by a resistor connected from PWM2 pin to GND. When PWM middle state is enabled, the uP9512R drives the PWM middle state voltage by itself. Otherwise, the PWM output of the controller is in high-impedance state, and then the PWM middle state voltage is determined by MOSFET driver. Table 3 lists the recommended  $R_{PWM2}$  value for APL hysteresis and the PWM middle state mode.

Table 3. APL Hysteresis and Recommended  $R_{PWM2}$  Value

Recommended $R_{PWM2}$ (k $\Omega$ )	APL_Hys	PWM Middle State
15	140mV	Disable
24	120mV	
36	100mV	
56	80mV	
68	60mV	
82	40mV	
100	20mV	
120	0mV	Enable
130	0mV	
150	20mV	
169	40mV	
180	60mV	
200	80mV	
215	100mV	
232	120mV	
280	140mV	

## Functional Description

### Operation Frequency and SMBus Device Address

The uP9512R features a multi-function pin (ADDR/FSW) to provide 5 SMBus device address and 8 operation frequency selection. Connect ADDR/FSW pin to 5VCC with a resistor divider (Figure 9) to set the operation frequency and SMBus device address. Table 4 shows the recommended  $R_{UP}$  and  $R_{DW}$  resistance of the resistor divider.

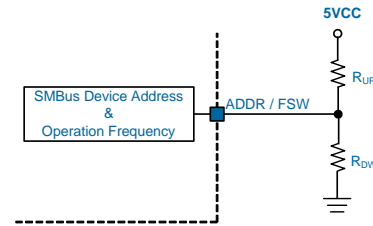


Figure 9. ADDR/FSW Pin Connection

Table 4. Operation Frequency and SMBus Device Address

$V_{ADDR/FSW} =$ % of 5VCC	Operation Frequency (Hz)	SMBus Device Address (Unit: k $\Omega$ )									
		0x48		0x4A		0x4C		0x4E		0x40	
		$R_{UP}$	$R_{DW}$	$R_{UP}$	$R_{DW}$	$R_{UP}$	$R_{DW}$	$R_{UP}$	$R_{DW}$	$R_{UP}$	$R_{DW}$
40.63%	200k	4.92	3.37	24.61	16.84	44.3	30.32	73.84	50.53	147.67	101.06
46.88%	300k	4.27	3.77	21.33	18.83	38.4	33.89	63.99	56.48	127.99	112.95
53.13%	400k	3.76	4.27	18.82	21.34	33.88	38.4	56.47	64.01	112.93	128.01
59.38%	500k	3.37	4.92	16.84	24.62	30.31	44.31	50.52	73.86	101.04	147.71
65.63%	600k	3.05	5.82	15.24	29.1	27.43	52.37	45.71	87.29	91.42	174.57
71.88%	1000k	2.78	7.11	13.91	35.56	25.04	64.01	41.74	106.69	83.47	213.37
78.13%	1500k	2.56	9.14	12.8	45.72	23.04	82.3	38.4	137.17	76.8	274.35
84.38%	2000k	2.37	12.8	11.85	64.02	21.33	115.24	35.55	192.06	71.11	384.12

### Phase Number of Operation (Hardware Programming)

The uP9512R supports 8/7/6/5/4/3/2/1-phase operation. The maximum phase number of operation is determined by checking the status of CSPx pins when power on reset. Please follow Table 5 for the phase disable. The maximum phase number of operation is decided and latched at each POR rising edge. The unused PWMx pins can be left floating only if PWM strap function is disabled.

Table 5. Operation Phase Number Settings

Configuration	Pin Configuration, Pull High to Target							
	CSP8	CSP7	CSP6	CSP5	CSP4	CSP3	CSP2	CSP1
8-phase	--	--	--	--	--	--	--	--
7-phase	5VCC	--	--	--	--	--	--	--
6-phase	X	5VCC	--	--	--	--	--	--
5-phase	X	X	5VCC	--	--	--	--	--
4-phase	X	X	X	5VCC	--	--	--	--
3-phase	X	X	X	X	5VCC	--	--	--
2-phase	X	X	X	X	X	5VCC	--	--
1-phase	X	X	X	X	X	X	5VCC	--

Note 1: "--" denotes normal connection.

Note 2: "x" denotes floating.

Note 3: Use 100k $\Omega$  pull up resistor when pull up to 5VCC

Note 4: Strictly follow the table for phase disable. Incorrect pin pull up /down connection may cause catastrophic fault during start up.



## Functional Description

### Cold Boot and Warm Boot

The uP9512R features programmable operation phase number of Cold Boot Mode and Warm Boot Mode. When  $PSI=Low$  and uP9512R first boots up (first time of 5VCC and EN goes high), controller will enter to Cold Boot Mode. Exclude the first boot up condition, when  $PSI=Low$  state and controller power up by EN control, then uP9512R will enter to Warm Boot Mode. Connect LPC pin to 5VCC with a voltage divider (Figure 10) to set the operation phase number of Cold Boot Mode and Warm Boot Mode. Figure 11 shows all the power states of uP9512R under each combination of 5VCC/EN/  $PSI/VID$  signal. Table 6 shows the recommended resistance of the voltage divider.

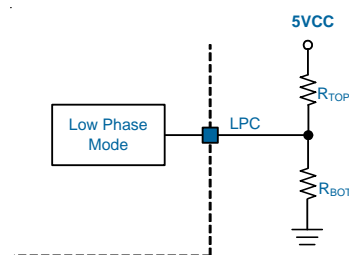


Figure 10. LPC Pin Connection

Table 6. Recommended Resistance of Cold Boot Mode and Warm Boot Mode

$V_{LPC} = \% \text{ of } 5VCC$	Cold Boot Phase Count	Warm Boot Phase Count (Unit: k $\Omega$ )									
		1-phase		2-phase		3-phase		4-phase		5-phase	
		$R_{TOP}$	$R_{BOT}$	$R_{TOP}$	$R_{BOT}$	$R_{TOP}$	$R_{BOT}$	$R_{TOP}$	$R_{BOT}$	$R_{TOP}$	$R_{BOT}$
40.63%	1-phase	4.92	3.37	24.61	16.84	44.3	30.32	73.84	50.53	147.67	101.06
46.88%	2-phase	4.27	3.77	21.33	18.83	38.4	33.89	63.99	56.48	127.99	112.95
53.13%	3-phase	3.76	4.27	18.82	21.34	33.88	38.4	56.47	64.01	112.93	128.01
59.38%	4-phase	3.37	4.92	16.84	24.62	30.31	44.31	50.52	73.86	101.04	147.71
65.63%	5-phase	3.05	5.82	15.24	29.1	27.43	52.37	45.71	87.29	91.42	174.57
71.88%	6-phase	2.78	7.11	13.91	35.56	25.04	64.01	41.74	106.69	83.47	213.37
78.13%	7-phase	2.56	9.14	12.8	45.72	23.04	82.3	38.4	137.17	76.8	274.35
84.38%	8-phase	2.37	12.8	11.85	64.02	21.33	115.24	35.55	192.06	71.11	384.12

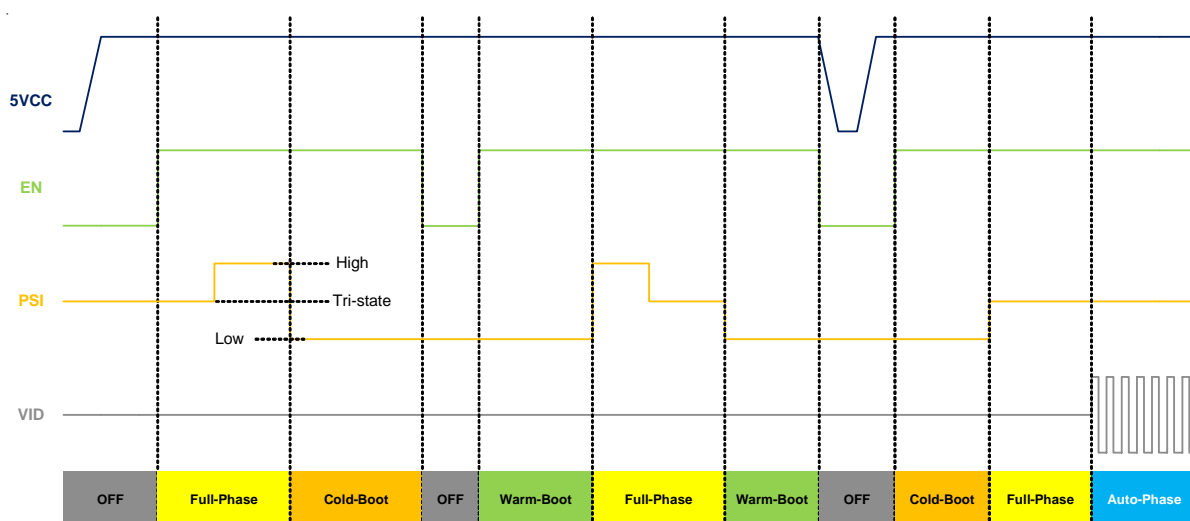


Figure 11. Power States of uP9512R

## Functional Description

### Channel Current Limit (CH\_OC)

The uP9512R adopts channel peak current limit function to avoid catastrophic damage to power stage components. The controller uses DCR current sensing technique to sense the inductor current (in the form of voltage) in each phase. If the sensed voltage of any phase exceeds the channel current limit threshold, the channel current limit function activates. The resistor  $R_{CH\_OC}$  connected between CH\_OC pin and GND determines the channel current limit threshold. The channel current limit threshold can be calculated as:

$$I_{OUT(PEAK)} = \frac{R_{CH\_OC} \times 20\mu A}{30 \times R_{DC}} + 10$$

Where  $I_{OUT(PEAK)}$  is the per-phase inductor peak current,  $R_{CH\_OC}$  is the resistor connected between CH\_OC pin and GND. Once the per-phase current exceeds the setting threshold, the per-phase output inductor current is limited to an average current. A continuous over load event will cause the output voltage drop and eventually trigger under voltage protection and shuts down the uP9512R.

### Total Output Current Protection

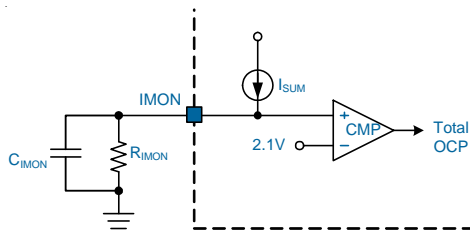


Figure 12. Total Output Current Protection

The uP9512R provides total OCP as shown in Figure 12. A resistor  $R_{IMON}$  is connected from IMON pin to GND. The sensed current  $I_{SUM}$  is mirrored internally and fed to IMON pin. This current flows through the resistor  $R_{IMON}$  creating voltage across it. As the total load current increases, the voltage on IMON pin ( $V_{IMON}$ ) increases proportionally. When the IMON pin voltage is greater than 2.1V, the total OCP will be triggered. The total OCP level (2.1V) is usually designed for the voltage regulator that is operated in full phase condition by hardware setting. The actual operating phase number is controlled by the PSI signal or the SMBus Auto Phase setting. When the operating phase number is decreased, the total OCP level is decreased as well. The total OCP level is changed per actual operating phase number. Table 7 shows the relationship between total OCP ratio per actual operating phase number and the hardware configuration. The total output current ( $I_{OUT\_MAX}$ ) of triggered OCP is calculated as:

$$I_{OUT\_MAX} = \frac{V_{OCP} - 0.1V}{R_{IMON}} \times \frac{N \times R_{SUM}}{R_{DC}}$$

The IMON pin has a 0.1V offset voltage, which means the IMON voltage increases from 0.1V as load current increases. The resistor  $R_{IMON}$  must be in the range of 10kΩ to 60kΩ. To ensure correct operation of the 0.1V offset mechanism, care must be taken when adding a capacitor to the IMON pin to adjust the IMON response time. The RC time constant must be adequate to ensure normal operation. Take  $R_{IMON} \times C_{IMON} < 5\mu$  as the rule of thumb when determining maximum  $C_{IMON}$ .

Once the total OCP is triggered. The uP9512R will turn off both high-side and low-side MOSFETs of all channels. The total OCP function is a latch-off function and only EN restart or 5VCC re-POR can release the latch.

Table 7. Total OCP and Operating Phase Number

Total Output OCP Ratio		Operating Condition							
		8-phase	7-phase	6-phase	5-phase	4-phase	3-phase	2-phase	1-phase
Hardware Configuration	8-phase	1	7/8	3/4	5/8	1/2	3/8	5/16	2/8
	7-phase	--	1	7/8	3/4	5/8	1/2	3/8	5/16
	6-phase	--	--	1	3/4	5/8	1/2	3/8	5/16
	5-phase	--	--	--	1	3/4	5/8	1/2	3/8
	4-phase	--	--	--	--	1	3/4	1/2	3/8
	3-phase	--	--	--	--	--	1	3/4	1/2
	2-phase	--	--	--	--	--	--	1	3/4
	1-phase	--	--	--	--	--	--	--	1



## Functional Description

### Ramp Slope Setting

The ramp slope of the oscillator for PWM modulation can be adjusted and is determined by the resistor  $R_{PWM7}$ . The setting for ramp slope and recommended  $R_{PWM7}$  resistance is shown in the table below.

$R_{PWM7}$	Ramp Slope
39k $\Omega$	50%
100k $\Omega$	75%
150k $\Omega$	100%
unstuffed	125%

### Thermal Protection (TSENSE)

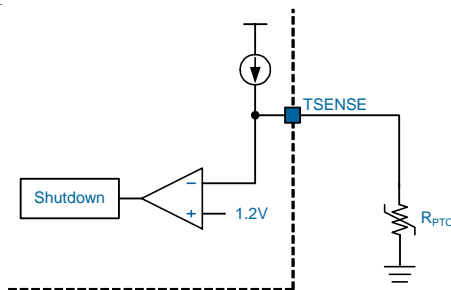


Figure 13. PTC Mode Circuit Connection

The uP9512R features a TSENSE pin to monitor the thermal condition of regulator. The uP9512R TSENSE pin supports positive temperature coefficient (PTC) thermistor protection network. Connect a PTC thermistor from TSENSE pin to GND to implement this function as shown in Figure 13. The PTC thermistor is placed close to the hottest point of the regulator, normally close to the inductor and the low-side MOSFET of phase1. A precision 120uA current source flows out from the TSENSE pin through the PTC thermistor and creates a voltage  $V_{TSENSE}$  on this pin. As regulator temperature rises, the  $V_{TSENSE}$  increases. If the  $V_{TSENSE}$  is higher than the 1.2V, the controller shuts down.

### Over Voltage Protection (OVP)

The OVP is triggered if  $V_{FB} > 1.5 \times V_{EAP}$  sustained 5us. When OVP is activated, the uP9512R turns on all low-side MOSFETs and turns off all high-side MOSFETs. The over voltage protection is a latch-off function and can only be reset by 5VCC re-POR or EN restart.

### Under Voltage Protection (UVP)

The under voltage protection is triggered if  $V_{FB} < 0.5 \times V_{EAP}$  sustained 5us. When UVP is activated, the uP9512R turns off all high-side and low-side MOSFETs. The under voltage protection is a latch-off function and can only be reset by 5VCC re-POR or EN restart.

### Over Temperature Protection (OTP)

The uP9512R monitors the temperature of itself. If the temperature exceeds typical 160°C, the uP9512R is forced into shutdown mode. The over temperature protection is a latch-off function and can only be reset by 5VCC re-POR or EN restart.

### SMBus ( SCL & SDA )

The uP9512R features an SMBus interface to allow user to adjust various operating parameters. The supported operating parameters that can be adjusted through the SMBus are summarized as Table 8. The main function is to dynamically change the offset voltage, switching frequency, operating phase number, and load line according to the total load current. This function is referred to Auto Phase, and it provides user the maximal flexibility in the platform design to maximize voltage regulator's efficiency and performance as well. The SMBus interface default is locked, it can be "read only" before it is unlocked. It writes 94h value in the register 0x39h to unlock the SMBus and writes 87h value to lock the SMBus interface. The SMBus provides one time lock/unlock mechanism. Once it is unlocked and locked, it cannot be unlocked again. It can only be reset by 5VCC re-cycle.

If the SMBus interface is not available in the platform design, the SDA and SCL pins can also be the hardware programming pins to program the operation mode when controller is working in single-phase operation. The uP9512R detects the state of SCL and SDA pins right on power on reset (POR) to recognize whether the SMBus is used or SCL and SDA becomes hardware programming pins. If SCL pin is "high" when POR, it becomes SMBus programming pins and the controller latched at CCM operation mode when controller is working in single-phase operation. If the SCL pin is "low" when POR, it becomes hardware programming pins and the controller latched at DCM mode when controller is working in single-phase operation. Then, the SDA pin is used to program the PWM output behavior of DCM operation mode as the following table.

SCL	SDA	Single Phase Operation Mode
0	0	Controller Controlled ZCD
0	1	MOSFET Driver Controlled ZCD
1	x	Forced CCM Mode

"0": Denotes the voltage is lower than 1V  
 "1": Denotes the voltage is higher than 1.2V  
 "x": Don't care

## Functional Description

When SCL=0 and SDA=0, the zero current detection (ZCD) is controlled by uP9512R controller. When the zero inductor current is detected, the controller sets the PWM output from low to high impedance state or sets PWM output to middle state level (depends on PWM2 setting) and turns off the low side MOSFET, then the controller runs in discontinuous conduction mode (DCM). When SCL=0 and SDA=1, the zero current detection is controlled by MOSFET driver itself. The uP9512R sets the PWM output from high to middle state level after a effective PWM duty cycle. When the companion MOSFET driver receives the PWM middle voltage from uP9512R controller, the MOSFET driver decides the discontinuous conduction mode (DCM) or continuous conduction mode (CCM) by itself according to output loading.

### **APL1, APL2, APL3, APL4 : (Reg0x01 ~ Reg0x04)**

Define the thresholds for five load current states (LCS0, LCS1, LCS2, LCS3 and LCS4). The controller compares the APL1, APL2, APL3 and APL4 content with  $V_{IMON}$  voltage to determine which load current state should be entered and executes the corresponding operating parameter settings (frequency, offset, operating phase number and load line).

LCS0 :  $V_{IMON} > APL4$ , highest load current state.

LCS1 :  $APL4 > V_{IMON} > APL3$

LCS2 :  $APL3 > V_{IMON} > APL2$

LCS3 :  $APL2 > V_{IMON} > APL1$

LCS4 :  $APL1 > V_{IMON}$ , lowest load current state.

### **APL\_Hys1, APL\_Hys2, APL\_Hys3, APL\_Hys4 : (Reg0x05~Reg0x06)**

Define the hysteresis voltage of APL1, APL2, APL3 and APL4. 8-bits content setting with 10mV/step

### **IICP0, IICP1, IICP2, IICP3, IICP4 : (Reg0x07 ~ Reg0x09)**

Define the operating phase number in each load current state. The operating phase number can be full-phase to single phase.

### **VOFS0, VOFS1, VOFS2, VOFS3, VOFS4: (Reg0x0A~Reg0x0C)**

Define the offset voltage in each load current state. 4-bits content setting with 10mV/step.

### **IICF0, IICF1, IICF2, IICF3, IICF4 : (Reg0x0D ~ Reg0x0F)**

Define the switching frequency in each load current state. The switching frequency is defined as the ratio to current operation frequency setting.

### **Current Balance Gain Adjustment : (Reg0x12 ~ Reg0x19)**

The uP9512R provides the current balance gain adjustment for user to optimize the performance in the system application. The current balance gain adjustment is defined as the ratio to default setting.

### **Current Balance Offset Adjustment :**

#### **(Reg0x1A ~ Reg0x1D)**

uP9512R features the current balance offset adjustment for user to optimize the performance in the system application. 3-bits content setting with 0.4uA/step.

#### **Channel Current Limit (CH\_OC) : (Reg0x22)**

For per-channel current limit threshold adjustment. 8-bits content setting with 10mV/step.

#### **Total OCP : (Reg0x23)**

For total output current protection level adjustment. 8-bits content setting with 10mV/step. The total output current protection adjustment is defined as the ratio to default setting.

#### **T\_OCP/UV/OV : (Reg0x24)**

T\_OCP programs the delay time of total OCP. UV/OV is used for the threshold adjustment of UVP and OVP respectively.

#### **GCOMP : (Reg0x26)**

For OTA transconductance setting for voltage control loop. It is defined as the ratio to the default value of 1960uA/V.

#### **SL\_RAMP : (Reg0x3A)**

The slope adjustment of the RAMP signal. It is defined as the ratio to the default setting.

#### **IOUT : (Reg0x2C)**

This register reports total output current that is converted by internal ADC with 10mV/step.

#### **VOOUT : (Reg0x2D)**

This register reports total output voltage that is converted by internal ADC with 10mV/step.

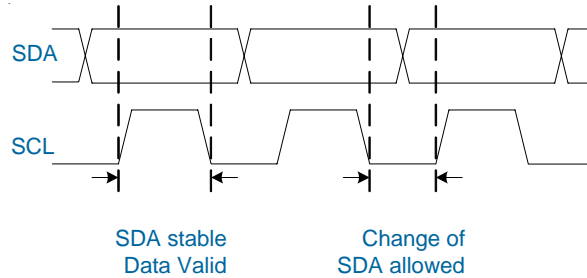
#### **TEMP : (Reg0x2E)**

This register reports temperature that is converted by internal ADC with 4.7mV/step.

## Functional Description

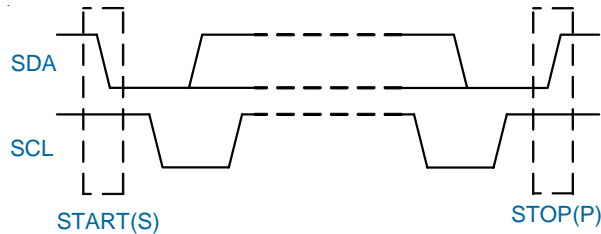
### Data Validity

The data on the SDA line must be stable during the HIGH period of the SCL, unless generating a START or STOP condition. The HIGH or LOW state of the data line can only change when the clock signal on the SCL line is LOW. Refer to the figure below.



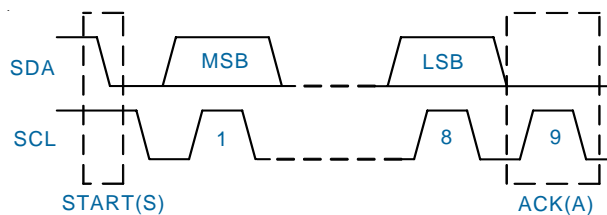
### START and STOP Conditions

A START (S) condition is a HIGH to LOW transition of SDA while SCL is HIGH. The STOP (P) condition is a LOW to HIGH transition of SDA while SCL is HIGH. A STOP condition must be sent before each START condition.



### Acknowledge

Each address and data transmission uses 9 clock pulses. The ninth pulse is the acknowledge bit (A). After the start condition, the master sends 7 slave address bits and a R/W bit during the next 8 clock pulses. During the ninth clock pulse, the device that recognizes its own address pulls SDA low to acknowledge. The acknowledge bit is also used by both the master and the slave to acknowledge receipt of register addresses and data.



### Read and Write Protocol

Write to a Single Register

S	slave_addr+W	AS	reg_addr	AS	reg_data	AS	P
---	--------------	----	----------	----	----------	----	---

Read from a Single Register

S	slave_addr+W	AS	reg_addr	AS	S	slave_addr+R	AS	reg_data	NA	P
---	--------------	----	----------	----	---	--------------	----	----------	----	---

S = START, P = STOP, AS = ACK from slave, AM = ACK from master, NA = No ACK

**Functional Description**

Table 8. SMBus Configuration Register

Register Address	Register Name	Access	Default	Description
0x01	APL1[7:0]	R/W	00h	Set Auto Phase Shedding Threshold 1 0V ~ 630mV(10mV / step) $V_{IMON} < V_{APL1} \Rightarrow$ LCS4 (lowest load current state)
0x02	APL2[7:0]	R/W	00h	Set Auto Phase Shedding Threshold 2 0V ~ 1.27V(10mV / step) $V_{APL1} < V_{IMON} < V_{APL2} \Rightarrow$ LCS3
0x03	APL3[7:0]	R/W	00h	Set Auto Phase Shedding Threshold 3 0V ~ 2.55V(10mV / step) $V_{APL2} < V_{IMON} < V_{APL3} \Rightarrow$ LCS2
0x04	APL4[7:0]	R/W	00h	Set Auto Phase Shedding Threshold 4, 0V ~ 2.55V(10mV / step) $V_{APL3} < V_{IMON} < V_{APL4} \Rightarrow$ LCS1 $V_{IMON} > V_{APL4} \Rightarrow$ LCS0 (highest load current state)
0x05	PWM_Mid[7] APL_Hys1[6:4] APL_Hys2[2:0]	R/W	55h	PWM_Mid[7] : Controller driving PWM middle state voltage "0" : Disable "1" : Enable APL_Hys1[6:4] : Hysteresis of APL1 threshold 0mV ~ 140mV (20mV / step) APL_Hys2[2:0] : Hysteresis of APL2 threshold 0mV ~ 140mV (20mV / step)
0x06	APL_Hys3[6:4] APL_Hys4[2:0]	R/W	55h	Bit[7] & Bit[3] : Don't Care. APL_Hys3[6:4] : Hysteresis of APL3 threshold 0mV ~ 140mV (20mV / step) APL_Hys4[2:0] : Hysteresis of APL4 threshold 0mV ~ 140mV (20mV / step)
0x07	IICP0[6:4] IICP1[2:0]	R/W	75h	Bit[7] & Bit[3] : Don't care. IICP0[6:4] : Operation phase number of LCS0. Default = 8-phase IICP1[2:0] : Operation phase number of LCS1. Default = 6-phase 000 : 1 phase ; 001 : 2 phase ; 010 : 3 phase ; 011 : 4 phase 100 : 5 phase ; 101 : 6 phase ; 110 : 7 phase ; 111 : 8 phase
0x08	IICP2[6:4] IICP3[2:0]	R/W	31h	Bit[7] & Bit[3] : Don't care. IICP2[6:4] : Operation phase number of LCS2. Default = 4-phase IICP3[2:0] : Operation phase number of LCS3. Default = 2-phase 000 : 1 phase ; 001 : 2 phase ; 010 : 3 phase ; 011 : 4 phase 100 : 5 phase ; 101 : 6 phase ; 110 : 7 phase ; 111 : 8 phase
0x09	IICP4[6:4]	R/W	00h	Bit[7] & Bit[3:0] : Don't care. IICP4[6:4] : Operation phase number of LCS4. Default = 1-phase 000 : 1 phase ; 001 : 2 phase ; 010 : 3 phase ; 011 : 4 phase 100 : 5 phase ; 101 : 6 phase ; 110 : 7 phase ; 111 : 8 phase
0x0A	IICV0[7:4] IICV1[3:0]	R/W	00h	IICV0[7:4] : Voltage offset of LCS0. 0mV ~ 150mV( 10mV / step ). Default = 0mV IICV1[3:0] : Voltage offset of LCS1. 0mV ~ 150mV( 10mV / step ). Default = 0mV

## Functional Description

Register Address	Register Name	Access	Default	Description
0x0B	IICV2[7:4] IICV3[3:0]	R/W	00h	IICV2[7:4] : Voltage offset of LCS2. 0mV ~ 150mV( 10mV / step ). Default = 0mV IICV3[3:0] : Voltage offset of LCS3. 0mV ~ 150mV( 10mV / step ). Default = 0mV
0x0C	IICV4[7:4]	R/W	00h	IICV4[7:4] : Voltage offset of LCS4. 0mV ~ 150mV( 10mV / step ). Default = 0mV
0x0D	IICF0[7:4] IICF1[3:0]	R/W	88h	IICF0[7:4] : Operation frequency of LCS0. IICF1[3:0] : Operation frequency of LCS1. 0000 : 60% ; 0001 : 65% ; 0010 : 70% ; 0011 : 75% ; 0100 : 80% ; 0101 : 85% ; 0110 : 90% ; 0111 : 95% ; 1000 : 100% (default) ; 1001 : 125% ; 1010 : 150% ; 1011 : 175% ; 1100 : 200% ; 1101 : 225% ; 1110 : 250% ; 1111 : 275%
0x0E	IICF2[7:4] IICF3[3:0]	R/W	88h	IICF2[7:4] : Operation frequency of LCS2. IICF3[3:0] : Operation frequency of LCS3. 0000 : 60% ; 0001 : 65% ; 0010 : 70% ; 0011 : 75% ; 0100 : 80% ; 0101 : 85% ; 0110 : 90% ; 0111 : 95% ; 1000 : 100% (default) ; 1001 : 125% ; 1010 : 150% ; 1011 : 175% ; 1100 : 200% ; 1101 : 225% ; 1110 : 250% ; 1111 : 275%
0x0F	IICF4[7:4] IICLL0[2:0]	R/W	84h	Bit [3]: Don't care. IICF4[7:4] : Operation frequency of LCS4. 0000 : 60% ; 0001 : 65% ; 0010 : 70% ; 0011 : 75% ; 0100 : 80% ; 0101 : 85% ; 0110 : 90% ; 0111 : 95% ; 1000 : 100% (default) ; 1001 : 125% ; 1010 : 150% ; 1011 : 175% ; 1100 : 200% ; 1101 : 225% ; 1110 : 250% ; 1111 : 275% IICLL0[2:0] : Load line setting of LCS0. 000 : 0% ; 001 : 25% ; 010 : 50% ; 011 : 75% 100 : 100%(default) ; 101 : 125% ; 110 : 150% ; 111 : 175%
0x10	IICLL1[6:4] IICLL2[2:0]	R/W	44h	Bit[7] & Bit[3] : Don't care. IICLL1[6:4] : Load line setting of LCS1. IICLL2[2:0] : Load line setting of LCS2. 000 : 0% ; 001 : 25% ; 010 : 50% ; 011 : 75% ; 100 : 100%(default) ; 101 : 125% ; 110 : 150% ; 111 : 175%
0x11	IICLL3[6:4] IICLL4[2:0]	R/W	44h	Bit[7] & Bit[3] : Don't care. IICLL3[6:4] : Load line setting of LCS3. IICLL4[2:0] : Load line setting of LCS4. 000 : 0% ; 001 : 25% ; 010 : 50% ; 011 : 75% ; 100 : 100%(default) ; 101 : 125% ; 110 : 150% ; 111 : 175%

## Functional Description

Register Address	Register Name	Access	Default	Description
0x12	CB_EN[7] PH8_IGAIN[6:2]	R/W	BCh	CB_EN[7] : On/Off control of current balance function, default = ON. "0" = OFF (current balance function is disabled) "1" = ON (current balance function is enabled) PH8_IGAIN[6:2] : PHASE8 current balance gain adjustment. PH8_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%.
0x13	PH7_IGAIN[6:2]	R/W	3Ch	PH7_IGAIN[6:2] : PHASE7 current balance gain adjustment. PH7_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%.
0x14	PH6_IGAIN[6:2]	R/W	3Ch	PH6_IGAIN[6:2] : PHASE6 current balance gain adjustment. PH6_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%.
0x15	PH5_IGAIN[6:2]	R/W	3Ch	PH5_IGAIN[6:2] : PHASE5 current balance gain adjustment. PH5_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%.
0x16	PH4_IGAIN[6:2]	R/W	3Ch	PH4_IGAIN[6:2] : PHASE4 current balance gain adjustment. PH4_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%.
0x17	PH3_IGAIN[6:2]	R/W	3Ch	PH3_IGAIN[6:2] : PHASE3 current balance gain adjustment. PH3_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%.
0x18	PH2_IGAIN[6:2]	R/W	3Ch	PH2_IGAIN[6:2] : PHASE2 current balance gain adjustment. PH2_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%.
0x19	PH1_IGAIN[6:2]	R/W	3Ch	PH1_IGAIN[6:2] : PHASE1 current balance gain adjustment. PH1_IGAIN = 243.75% - Bit[6:2] x 6.25%, default = 150%.
0x1A	PH8_IOS[6:4] PH7_IOS[2:0]	R/W	00h	Bit[7] & Bit[3] : Don't care. PH8_IOS[6:4] : PHASE8 current balance offset adjustment, default = 0uA. PH7_IOS[2:0] : PHASE7 current balance offset adjustment, default = 0uA. 000 : 0uA ; 001 : 0.4uA ; 010 : 0.8uA ; 011 : 1.2uA ; 100 : 1.6uA ; 101 : 2.0uA ; 110 : 2.4uA ; 111 : 2.8uA
0x1B	PH6_IOS[6:4] PH5_IOS[2:0]	R/W	00h	Bit[7] & Bit[3] : Don't care. PH6_IOS[6:4] : PHASE6 current balance offset adjustment, default = 0uA. PH5_IOS[2:0] : PHASE5 current balance offset adjustment, default = 0uA. 000 : 0uA ; 001 : 0.4uA ; 010 : 0.8uA ; 011 : 1.2uA ; 100 : 1.6uA ; 101 : 2.0uA ; 110 : 2.4uA ; 111 : 2.8uA
0x1C	PH4_IOS[6:4] PH3_IOS[2:0]	R/W	00h	Bit[7] & Bit[3] : Don't care. PH4_IOS[6:4] : PHASE4 current balance offset adjustment, default = 0uA. PH3_IOS[2:0] : PHASE3 current balance offset adjustment, default = 0uA. 000 : 0uA ; 001 : 0.4uA ; 010 : 0.8uA ; 011 : 1.2uA ; 100 : 1.6uA ; 101 : 2.0uA ; 110 : 2.4uA ; 111 : 2.8uA
0x1D	PH2_IOS[6:4] PH1_IOS[2:0]	R/W	00h	Bit[7] & Bit[3] : Don't care. PH2_IOS[6:4] : PHASE2 current balance offset adjustment, default = 0uA. PH1_IOS[2:0] : PHASE1 current balance offset adjustment, default = 0uA. 000 : 0uA ; 001 : 0.4uA ; 010 : 0.8uA ; 011 : 1.2uA ; 100 : 1.6uA ; 101 : 2.0uA ; 110 : 2.4uA ; 111 : 2.8uA



**Functional Description**

Register Address	Register Name	Access	Default	Description
0x1E	POCGAIN8[7:4] POCGAIN7[3:0]	R/W	BBh	POCGAIN8[7:4] : PHASE8 channel current limit gain adjustment, default = 100%. POCGAIN7[3:0] : PHASE7 channel current limit gain adjustment, default = 100%. 0000 : 237.5% ; 0001 : 225% ; 0010 : 212.5% ; 0011 : 200% ; 0100 : 187.5% ; 0101 : 175% ; 0110 : 162.5% ; 0111 : 150% ; 1000 : 137.5% ; 1001 : 125% ; 1010 : 112.5% ; 1011 : 100% ; 1100 : 87.5% ; 1101 : 75% ; 1110 : 62.5% ; 1111 : 50%
0x1F	POCGAIN6[7:4] POCGAIN5[3:0]	R/W	BBh	POCGAIN6[7:4] : PHASE6 channel current limit gain adjustment, default = 100%. POCGAIN5[3:0] : PHASE5 channel current limit gain adjustment, default = 100%. 0000 : 237.5% ; 0001 : 225% ; 0010 : 212.5% ; 0011 : 200% ; 0100 : 187.5% ; 0101 : 175% ; 0110 : 162.5% ; 0111 : 150% ; 1000 : 137.5% ; 1001 : 125% ; 1010 : 112.5% ; 1011 : 100% ; 1100 : 87.5% ; 1101 : 75% ; 1110 : 62.5% ; 1111 : 50%
0x20	POCGAIN4[7:4] POCGAIN3[3:0]	R/W	BBh	POCGAIN4[7:4] : PHASE4 channel current limit gain adjustment, default = 100%. POCGAIN3[3:0] : PHASE3 channel current limit gain adjustment, default = 100%. 0000 : 237.5% ; 0001 : 225% ; 0010 : 212.5% ; 0011 : 200% ; 0100 : 187.5% ; 0101 : 175% ; 0110 : 162.5% ; 0111 : 150% ; 1000 : 137.5% ; 1001 : 125% ; 1010 : 112.5% ; 1011 : 100% ; 1100 : 87.5% ; 1101 : 75% ; 1110 : 62.5% ; 1111 : 50%
0x21	POCGAIN2[7:4] POCGAIN1[3:0]	R/W	BBh	POCGAIN2[7:4] : PHASE2 channel current limit gain adjustment, default = 100%. POCGAIN1[3:0] : PHASE1 channel current limit gain adjustment, default = 100%. 0000 : 237.5% ; 0001 : 225% ; 0010 : 212.5% ; 0011 : 200% ; 0100 : 187.5% ; 0101 : 175% ; 0110 : 162.5% ; 0111 : 150% ; 1000 : 137.5% ; 1001 : 125% ; 1010 : 112.5% ; 1011 : 100% ; 1100 : 87.5% ; 1101 : 75% ; 1110 : 62.5% ; 1111 : 50%
0x22	CH_OC[7:0]	R/W	--	CH_OC[7:0] : Channel current limit threshold adjustment. $V_{CH\_OC} = Bit[7:0] \times 10mV$
0x23	Total_OCP[2:0]	R/W	00h	Bit [7:3] : Don't care. Total_OCP[2:0] : Total output current protection threshold adjustment. 000 : 100% (default) ; 001 : 001% ; 010 : 120% ; 011 : 130% 100 : 140% ; 101 : 150% ; 110 : 160% ; 111 : 170%
0x24	T_OCP[7:6] UV[5:3] OV[2:0]	R/W	1Bh	T_OCP[7:6] : Total output current protection delay time adjustment. 00 : 20us (default) ; 01 : 10us ; 10 : 6.67us ; 11 : 5us UV[5:3] : Under voltage protection threshold adjustment. 000 : 30% ; 001 : 35% ; 010 : 40% ; 011 : 45% (default) 100 : 50% ; 101 : 55% ; 110 : 60% ; 111 : 65% OV[2:0] : Over voltage protection threshold adjustment. 000 : 140% ; 001 : 145% ; 010 : 150% ; 011 : 155% (default) 100 : 160% ; 101 : 165% ; 110 : 170% ; 111 : 175%

**Functional Description**

Register Address	Register Name	Access	Default	Description
0x26	GCOMP[3:0]	R/W	00h	Bit[7:4] : Don't care. GCOMP[3:0] : OTA Gm value selection, default = 1960uA/V. 000 : 1960uA/V; 001: 2300uA/V ; 010 : 2610uA/V ; 011 : 2890uA/V ; 100 : 3380uA/V ; 101 : 1580uA/V ; 110 : 1150uA/V ; 111 : 636uA/V
0x2A	Misc2[6:2]	R/W	24h	Bit[6]: Output voltage offset enable control "0" = Disable Offset(default) "1" = Enable Offset Bit[5] : Auto Phase H/W setting enable control "0" = Ignore H/W setting "1" = Follow H/W setting (default) Bit[4]: Auto Phase enable control (when Bit[5]=0) "0" = Disable Auto Phase (forced full phase operation) (default) "1" = Enable Auto Phase Bit[3]: DCM enable control when in 1-phase operation "0" = Disable DCM (default) "1" = Enable DCM Bit[2]: Forced full phase operation when channel OCL is triggered at APS Mode. "0" = Disable "1" = Enable (default)
0x2C	IOUT[7:0]	RO	--	Total output current reporting, ADC result of IMON voltage. (10mV/step)
0x2D	VOUT[7:0]	RO	--	Output voltage reporting. (sense VOUT voltage) (10mV/step)
0x2E	TEMP[7:0]	RO	--	Temperature reporting. ADC result of TSENSE voltage. (4.7mV/step)
0x33	ZC_OFFSET[7:5] T_PH_DW[4:2] OTP[1]	R/W	26h	ZC_OFFSET[7:5]: ZC offset adjustment. 000:0mV; 001: 1mV(default); 010: 1.33mV 011: 1.67mV;100: 2mV; 101: 2.33mV; 110: 2.67mV;111: 3mV T_PH_DW[4] : Down phase delay control. "0" : Disable (default) "1" : Enable T_PH_DW[3:2] : Down phase delay time 00=10us 01=20us(default) 10=40us 11=80us OTP[1] : OTP protection control. "0" : Disable "1" : Enable (default)
0x35	PROT_IND2[7:0]	RO	00h	Each channel OCL indicator. Bit[7] : PHASE8 channel OCL indicator Bit[6] : PHASE7 channel OCL indicator Bit[5] : PHASE6 channel OCL indicator Bit[4] : PHASE5 channel OCL indicator Bit[3] : PHASE4 channel OCL indicator Bit[2] : PHASE3 channel OCL indicator Bit[1] : PHASE2 channel OCL indicator Bit[0] : PHASE1 channel OCL indicator "0" = Not Active "1" = Active



## Functional Description

Register Address	Register Name	Access	Default	Description
0x37	PWM1_H_Mid[2]	R/W	00h	PWM1_H_Mid[2] : PWM1 output switching behavior control. Once it is enabled, only PWM1 output switching behavior changes from "High -> Low" to "High -> Middle", other PWM outputs keep "High -> Low" switching behavior. "0" : Disable "1" : Enable
0x38	ACLL[7:5] V_OCL_MIN[4:2] IOUT_AVG_SR[1:0]	R/W	2Ch	Bit[7]: AC load line control. "0" : Follow HW setting (default) "1" : Enable AC Load Line Bit[6:5]: AC load line response time 00=40us 01=80us(default) 10=120us 11=160us Bit[4]: OCL disable if REFIN < V_OCL_Min "0" = Disable(default) "1" = Enable Bit[3:2]: OCL disable if REFIN voltage reaches below threshold. "00"=0.3V ; "01"=0.4V ; "10"=0.5V ; "11"=0.6V(default) Bit[1:0]: Sample rate of IOUT_AVG. "00"=50us(default) ; "01"=200us ; "10"=800us ; "11"=3200us
0x39	SMBus_Lock[7:0]	R/W	00h	SMBus_Lock[7:0] : SMBus register security lock. SMBus register default is locked, all the registers are "read only" and cannot be modified before unlock. Once the SMBus unlock and lock again, it needs VCC re-POR to reset. Bit[7:0] = "94h" , unlock SMBus Bit[7:0] = "87h" , lock SMBus
0x3A	SL_RAMP[7:6]	R/W	C0h	SL_RAMP[7:6] : RAMP slope adjustment. 00 : 01 : 75% ; 10 : 100% ; 11 : 125%(default)
0x3B	PROT_IND[7:3] OP_PH_MON[2:0]	RO	00h	Protection indication, indicating which protection is triggered. Bit[7] : OTP indicator "0" = Not Active "1" = Active Bit[6] : Total OCP Indicator "0" = Not Active "1" = Active Bit[4] : OVP Indicator "0" = Not Active "1" = Active Bit[3] : UVP Indicator "0" = Not Active "1" = Active Bit[2:0] : Operating Phase Number Monitor 000 : 1 phase ; 001 : 2 phase ; 010 : 3 phase ; 011 : 4 phase 100 : 5 phase ; 101 : 6 phase ; 110 : 7 phase ; 111 : 8 phase

## Functional Description

Register Address	Register Name	Access	Default	Description
0x3C	Misc1[3:0]	R/W	0Fh	Bit[3]: Total OCP control "0" = Disable Total OCP function "1" = Enable Total OCP function(default) Bit[2]: Channel OCL Control "0" = Disable Channel OCL function "1" = Enable Channel OCL function(default) Bit[1]: OVP Control "0" = Disable OVP function "1" = Enable OVP function(default) Bit[0]: UVP Control "0" = Disable UVP function "1" = Enable UVP function(default)
0x3D	IOUT_AVG[7:0]	RO	00h	Average output current report, ADC result of $V_{IMON}$ . (10mV/step)
0x27	Vendor ID	RO	00h	
0x28	Device ID	RO	2Bh	

## Absolute Maximum Rating

(Note 1)

Supply Input Voltage, 5VCC	-0.3V to +6V
Other Pins	0.3V to +6V
Storage Temperature Range	-65°C to +150°C
Junction Temperature	150°C
Lead Temperature (Soldering, 10 sec)	260°C
ESD Rating (Note 2)	
HBM (Human Body Mode)	2kV

## Thermal Information

Package Thermal Resistance (Note 3)

VQFN5x5 - 40L $\theta_{JA}$	36°C/W
VQFN5x5 - 40L $\theta_{JC}$	3°C/W
Power Dissipation, $P_D$ @ $T_A = 25^\circ\text{C}$	
VQFN5x5 - 40L	2.78W

## Recommended Operation Conditions

(Note 4)

Operating Junction Temperature Range	-40°C to +125°C
Operating Ambient Temperature Range	-40°C to +85°C
Supply Input Voltage, 5VCC	4.5V to 5.5V
Power Stage Input Voltage, $V_{IN}$	3V to 20V

**Note 1.** Stresses listed as the above *Absolute Maximum Ratings* may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.

**Note 2.** Devices are ESD sensitive. Handling precaution recommended.

**Note 3.**  $\theta_{JA}$  is measured in the natural convection at  $T_A = 25^\circ\text{C}$  on a low effective thermal conductivity test board of JEDEC 51-3 thermal measurement standard.

**Note 4.** The device is not guaranteed to function outside its operating conditions.

## Electrical Characteristics

(5VCC = 5V,  $T_A = 25^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Supply Input</b>						
5VCC POR Threshold	$\text{POR}_{5\text{VCC}}$	5VCC rising	4	4.3	4.5	V
5VCC POR Hysteresis	$\text{HYS}_{5\text{VCC\_POR}}$		--	300	--	mV
Quiescent Current	$I_Q$	EN = high , No switching	--	7	--	mA
Shutdown Current	$I_{SD}$	EN = 0V	--	300	--	uA
<b>Power Stage Input Voltage Monitoring</b>						
VINMON Monitoring Range			0.3	--	2.4	V
VINMON Rising Threshold	$V_{\text{VINMON}}$		--	0.2	--	V
VINMON Hysteresis	$V_{\text{VINMON\_HYS}}$		--	100	--	mV
<b>Enable Control</b>						
Logic Low	$V_{\text{IL\_EN}}$		--	--	0.1	V
Logic High	$V_{\text{IH\_EN}}$		0.2	--	--	V
<b>PWMVID Interface (VREF, VID, REFADJ, REFIN)</b>						
VREF Voltage Accuracy	$V_{\text{REF}}$		1.98	2	2.02	V
VREF Sourcing Current	$I_{\text{REF\_SRC}}$	VREF short to GND	10	--	--	mA
REFIN Disable Threshold	$V_{\text{REFIN\_DSB}}$		--	0.1	--	V
External Reference Voltage Range	$V_{\text{REFIN}}$		0.2	--	2	V
VID Input Low	$V_{\text{IL\_VID}}$		--	--	0.6	V
VID Input High	$V_{\text{IH\_VID}}$		1.2	--	--	V
VID Tri-state Voltage	$V_{\text{TRL\_VID}}$		--	0.9	--	V
VID Tri-state Delay	$T_{\text{TRL\_VID}}$	VID from High to Tri-state; VID from Low to Tri-state	--	100	--	ns
REFADJ Source Resistance	$R_{\text{BF\_SRC}}$	$I_{\text{SRC}} = 1\text{mA}$	--	20	--	$\Omega$
REFADJ Sink Resistance	$R_{\text{BF\_SNK}}$	$I_{\text{SINK}} = 1\text{mA}$	--	20	--	$\Omega$
<b>DAC Voltage Accuracy</b>						
DAC Output Accuracy	$V_{\text{DAC}}$	Load Line Disabled	-1	--	1	mV
<b>Oscillator</b>						
Operation Frequency Range	$F_{\text{SW}}$	Per-phase operation frequency	200	--	2000	kHz
Frequency Accuracy		Frequency setting to 300kHz	270	300	330	kHz
Maximum Duty Cycle	$D_{\text{MAX}}$	Ramp slope setting to 100%	--	45	--	%
Minimum PWM Pulse Width	$T_{\text{PWM\_MIN}}$	Guaranteed by design	--	40	--	ns

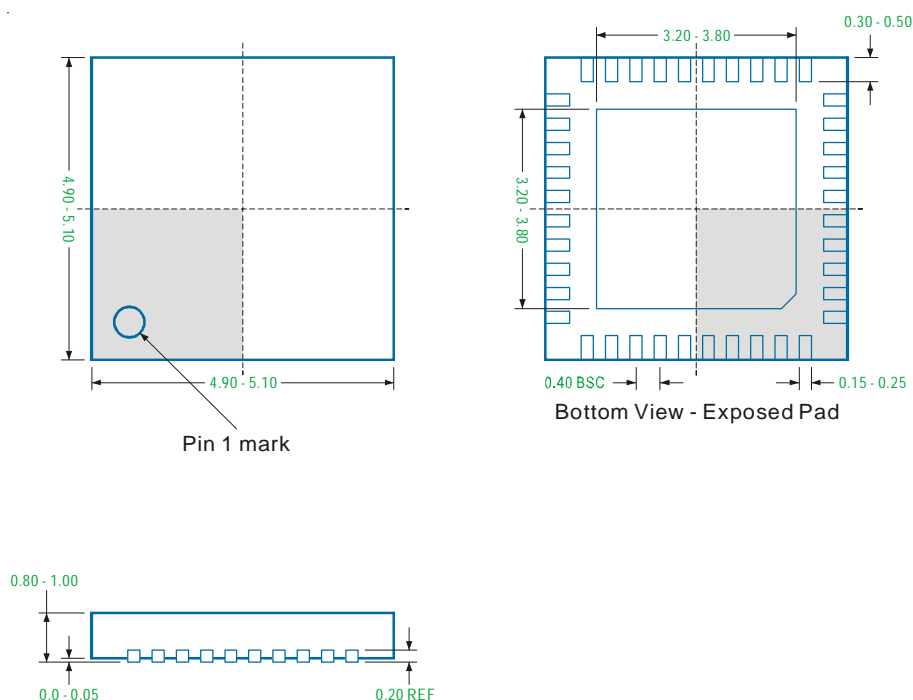
## Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Soft-Start						
Output Ramp Up Time	T <sub>RAMP</sub>	R <sub>PWM8</sub> = unstuffed	--	640	--	us
Initialization Time	T <sub>INIT</sub>	EN go high to Vout start up from 0V	--	550	--	us
Error Amplifier						
Offset Voltage	V <sub>OS(EA)</sub>		-1	--	1	mV
Input Bias Current	I <sub>EA</sub>	Guaranteed by design	-10	--	10	nA
Open Loop DC Gain	AO	Guaranteed by design	--	70	--	dB
Gain-Bandwidth Product	GBW	Guaranteed by design	--	10	--	MHz
Trans-conductance	GM		--	1960	--	uA / V
COMP Source Current	I <sub>COMP_SRC</sub>		--	300	--	uA
COMP Sink Current	I <sub>COMP_SNK</sub>		--	300	--	uA
FBRTN						
FBRTN Current	I <sub>FBRTN</sub>	EN = 1.8V, normal operation	--	--	100	uA
Current Summing Amplifier (CSPSUM & CSNSUM)						
Input Offset Voltage	V <sub>OFF_CSA</sub>	Guaranteed by design	-1	--	1	mV
Max Sourcing Current	I <sub>SRC_CSA</sub>		300	--	--	uA
Current Sense Amplifier ( CSP1~CSP8 )						
Input Offset Voltage	V <sub>OFF_CSA</sub>	Guaranteed by design	-1	--	1	mV
PWM Output (PWM1~PWM8)						
Output Low Voltage	V <sub>PWM_L</sub>	I <sub>SNK</sub> = 4mA	--	--	0.2	V
Output Hight Voltage	V <sub>PWM_H</sub>	I <sub>SOURCE</sub> = 4mA	4.7	--	--	V
High Impedance State Leakage		V <sub>PWM</sub> = 0V	-1	--	0	uA
		V <sub>PWM</sub> = 5V	0	--	1	uA
Source Current	I <sub>PWMx</sub>	R <sub>EN</sub> = 10kΩ; during T <sub>INIT</sub> time	--	10	--	uA
Power Saving Input (PSI)						
Power Saving Mode Logic	V <sub>PSI</sub>	Full-Phase Mode	1.4	--	--	V
		Auto-Phase Shedding Mode	0.8	--	1.2	
		Low-Phase Mode	--	--	0.4	
DC Load Line						
DC Load Line Enable Threshold		PWM1 resistor strap to GND	25	--	200	kΩ
DC Load Line Always Functional			250	--	--	kΩ

## Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>IMON</b>						
IMON Offset Voltage	$V_{OF}$	$10k\Omega \leq R_{IMON} \leq 60k\Omega$	--	0.1	--	V
$R_{IMON}$ Range	$R_{IMON}$		10	--	60	k $\Omega$
Current Mirror Accuracy		From $I_{SUM}$ to $I_{EAP}$ or $I_{MON}$	95	100	105	%
<b>Protection</b>						
Channel Current Limit Setting Current	$I_{CH\_OC}$		--	20	--	$\mu$ A
Total Over Current Protection (OCP) Threshold	$V_{OCP}$	Measure IMON voltage	--	2.1	--	V
Total Over Current Protection (OCP) Delay	$T_{OCP}$	$V_{IMON} > V_{OCP}$	--	20	--	$\mu$ s
Under Voltage Protection (UVP) Threshold	$V_{UVP}$		40	45	50	%
Under Voltage Protection (UVP) Delay	$T_{UVP}$		--	5	--	$\mu$ s
Over Voltage Protection (OVP) Threshold	$V_{OVP}$	$V_{FB}/V_{REFIN}$	150	155	160	%
Over Voltage Protection (OVP) Delay	$T_{OVP}$		--	5	--	$\mu$ s
Over Temperature Protection (OTP) Threshold	$T_{OTP}$	Guaranteed by design	--	160	--	$^{\circ}$ C
<b>Power Good Indicator</b>						
PGOOD Output Low Level	$V_{PG}$	$I_{SINK} = 4mA$	--	--	0.3	V
PGOOD Leakage Current	$I_{PG\_Leak}$	$V_{PGOOD} = 5V$	--	--	0.1	$\mu$ A
<b>SMBus Interface (SCL &amp; SDA)</b>						
Input Low Voltage	$V_{IL\_SMBus}$	Guaranteed by design	--	--	0.4	V
Input High Voltage	$V_{IH\_SMBus}$	Guaranteed by design	1.6	--	--	V
Pull Down Resistance	$R_{PULL\_SMBus}$	Guaranteed by design	--	8	--	$\Omega$
<b>Thermal Monitoring (TSENSE)</b>						
Source Current	$I_{TSENSE}$		--	120	--	$\mu$ A
Thermal Shutdown Threshold		PTC type application	--	1.2	--	V

VQFN5x5 - 40L



**Note**

**1. Package Outline Unit Description:**

BSC: Basic. Represents theoretical exact dimension or dimension target

MIN: Minimum dimension specified.

MAX: Maximum dimension specified.

REF: Reference. Represents dimension for reference use only. This value is not a device specification.

TYP: Typical. Provided as a general value. This value is not a device specification.

**2. Dimensions in Millimeters.**

**3. Drawing not to scale.**

**4. These dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm.**

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## VQFN5x5 Package

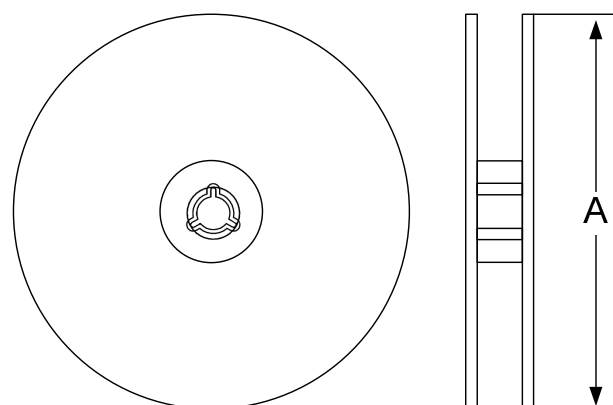
### Definition:

**QFN = Quad Flat No Lead**

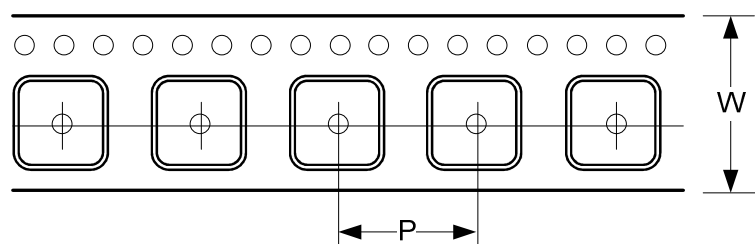
V Type= Very Thin Package(Thickness =  $0.9 \pm 0.1\text{mm}$ )

### Tape & Reel Drawing

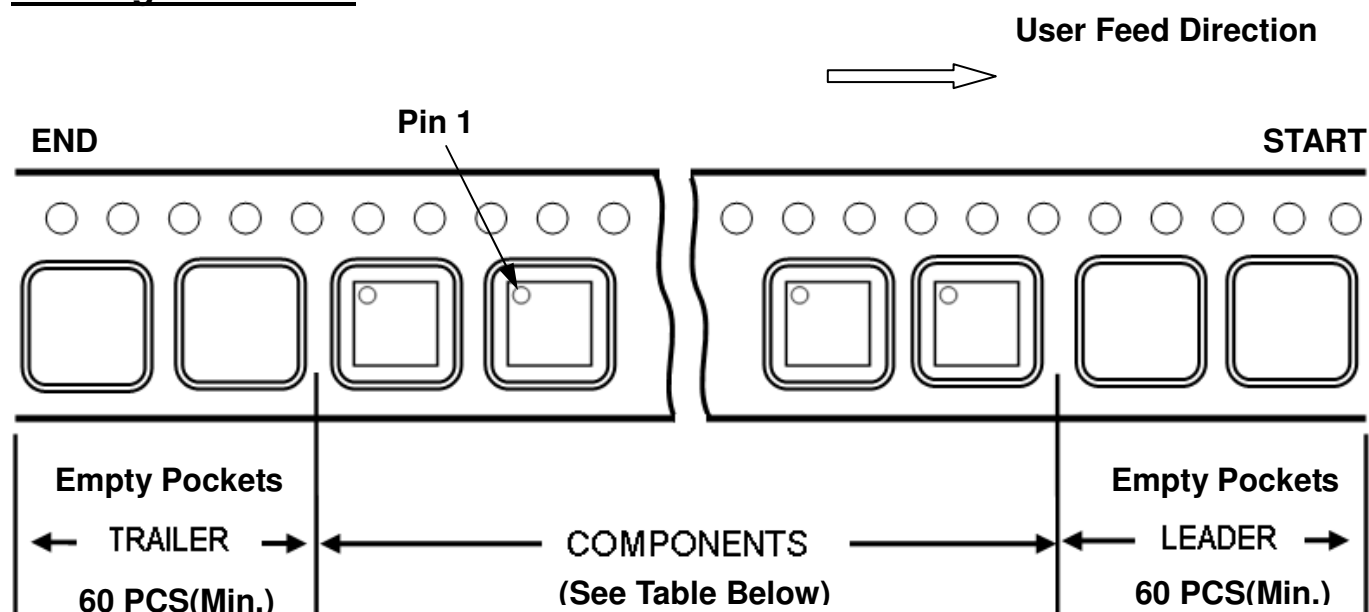
#### Lock Reel



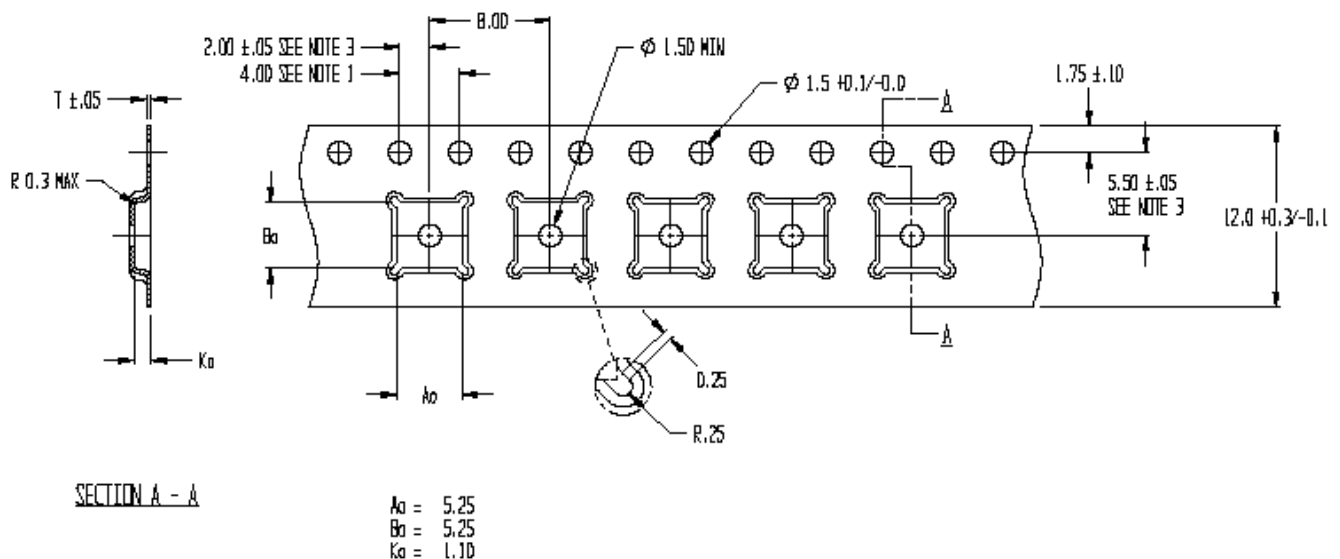
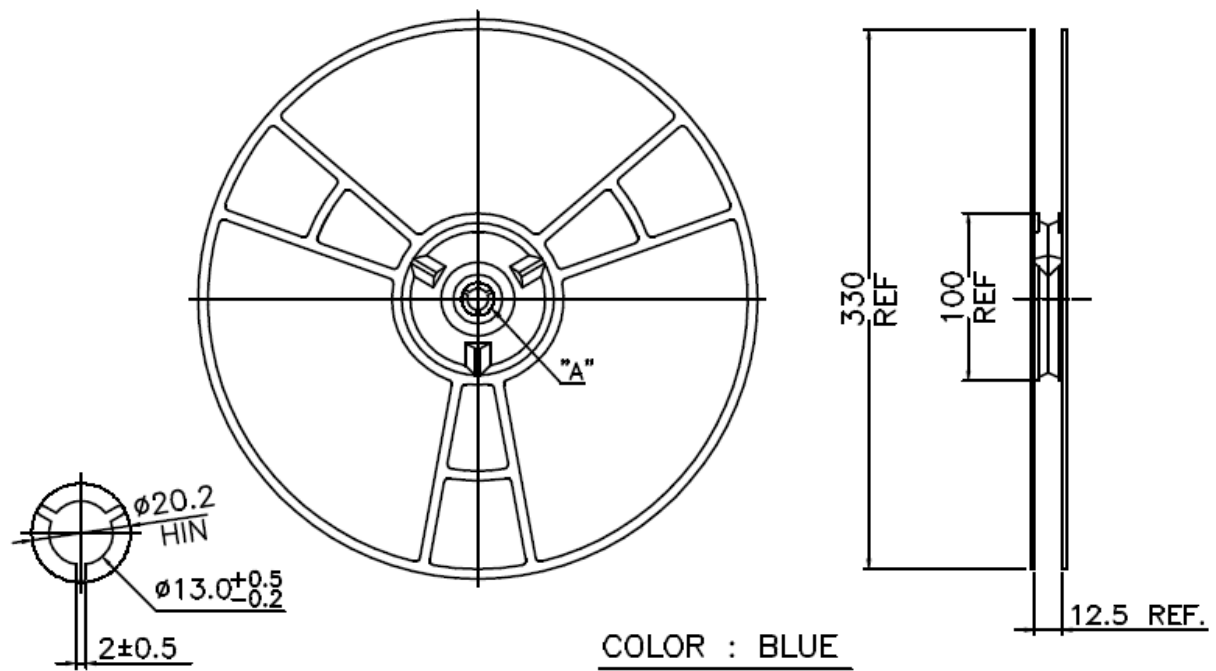
#### Carrier Tape



### Packing Illustration



## Carrier Tape Drawing



### Packing Quantity List

PKG Type Body Size	Reel Diameter(A) (inch/mm)	Carrier Width(W) (mm)	Carrier Pitch(P) (mm)	Reel Quantity (pcs)	Remark
VQFN 5x5	13 / 330	12	8	2500	

### *Packaging Drawing*

#### Barcode Label – Apply for Reel/AI Bag/Inner Box and Outer Carton

	
P/N: UP1234ABCD	QTY: 12345678
	
LOT: F1234.1.000	DATE: 2008.01.01
	
D/C: ABC123	Note:
	 

P/N : uPI Part Number

LOT : Wafer Lot Number

QTY : Packing Quantity

D/C : Manufacturing Date Code

DATE : Packing Date

Note : For Internal Use Only

#### Inner Box



**Box (13" Reel 355 x338 x 50 mm)**

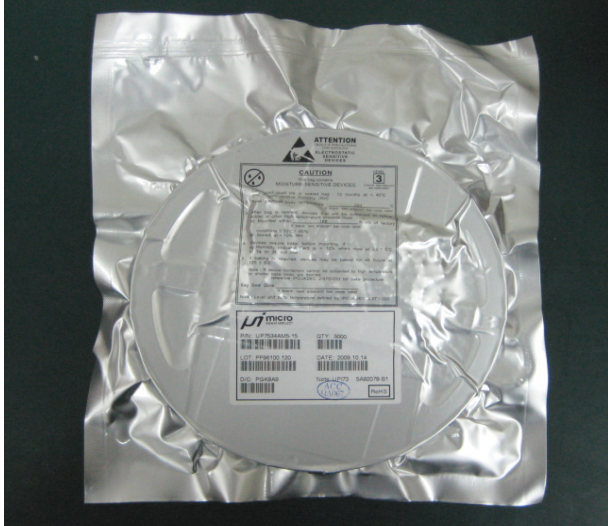
#### Outer Carton



**Carton A (382 x 283 x390 mm )**

**Package Storage Condition:**

- Vacuum Sealed into Moisture Barrier Bag and Meet MSL Level 3 requests.
- Comply with J-STD-033 standard.

**- Storage Condition**

Vacuum Sealed : 12 months at  $<40^{\circ}\text{C}$  and 90%RH

Bag Opened : Within 168 hrs at  $< 30^{\circ}\text{C}$  / 60%RH

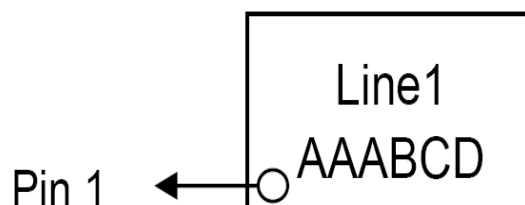
**- Baking Condition**

Re-Baking @  $125^{\circ}\text{C} \pm 5^{\circ}\text{C}$ , 48hrs for IC only;

Floor life begins counting at time =0 after Re-Baking.

The times of Re-Baking: 2 times, Max.

## Top Marking Rule



Line 1 : Product Code

Part No.	Product Code
uP9512RQGJ	uP9512R

Line 2 :

AAA - uPI internal trace code

BCD - Date Code, rules as below:

B : Last one of western calendar year (0~9), ex. 2007=7, 2008=8

C : Month

Month	Code	Month	Code	Month	Code	Month	Code
Jan	1	Apr	4	Jul	7	Oct	A
Feb	2	May	5	Aug	8	Nov	B
Mar	3	Jun	6	Sep	9	Dec	C

D : Date

Date	Code	Date	Code	Date	Code	Date	Code
1	1	9	9	17	H	25	S
2	2	10	A	18	J	26	T
3	3	11	B	19	K	27	U
4	4	12	C	20	L	28	V
5	5	13	D	21	M	29	W
6	6	14	E	22	N	30	X
7	7	15	F	23	P	31	Y
8	8	16	G	24	R		

## ***Pb-free Package Peak Reflow Temperatures***

Package Thickness	Volume mm <sup>3</sup> < 350	Volume mm <sup>3</sup> 350 -2000	Volume mm <sup>3</sup> > 2000
< 1.6 mm	260 +0 °C	260 +0 °C	260 +0 °C
1.6 mm - 2.5 mm	260 +0 °C	250 +0 °C	245 +0 °C
≥ 2.5 mm	250 +0 °C	245 +0 °C	245 +0 °C

## ***IR Reflow Profile***

Profile Feature	Pb-Free Assembly
Average Ramp-up Rate (TS <sub>max</sub> to Tp)	3 °C/second max.
Preheat - Temperature Min (TS <sub>min</sub> ) - Temperature Max (TS <sub>max</sub> ) - Time (TS <sub>min</sub> to TS <sub>max</sub> )	150 °C 200 °C 60-180 Seconds
Time Maintained above - Temperature (TL) - Time (tL)	217 °C 60-150 Seconds
Peak/Classification Temperature (Tp)	≤260 °C
Time Within 5 °C of actual Peak Temperature (tp)	20-40 seconds
Ramp-Down Rate	6 °C/second max.
Time 25 °C to Peak Temperature	8 minutes max.

